First Quarter FY 2026 Quarterly Update

Infineon Technologies AG
Investor Relations

Infineon at a glance

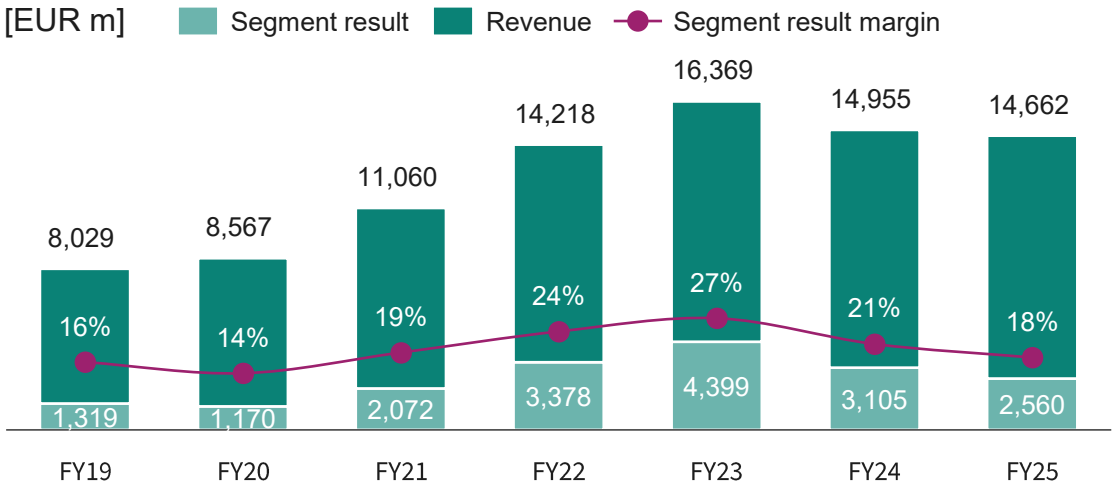
Addressing long-term high-growth trends

Energy
green and efficient

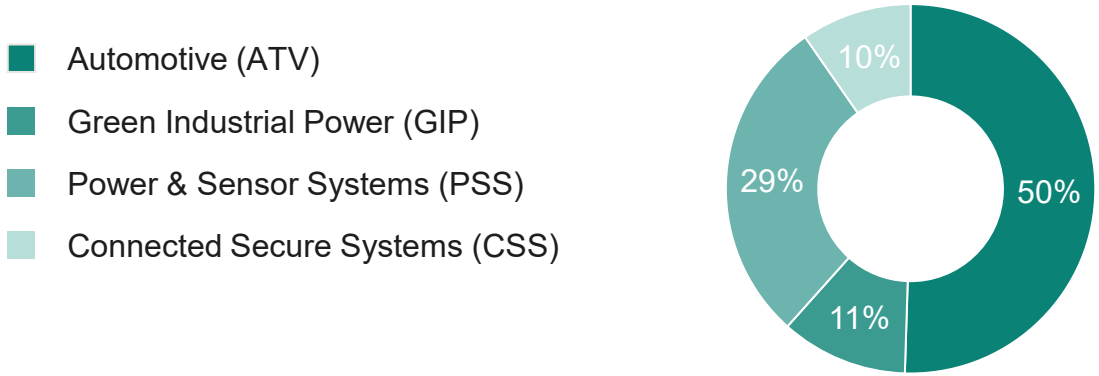
Mobility
clean and safe

IoT
smart and secure

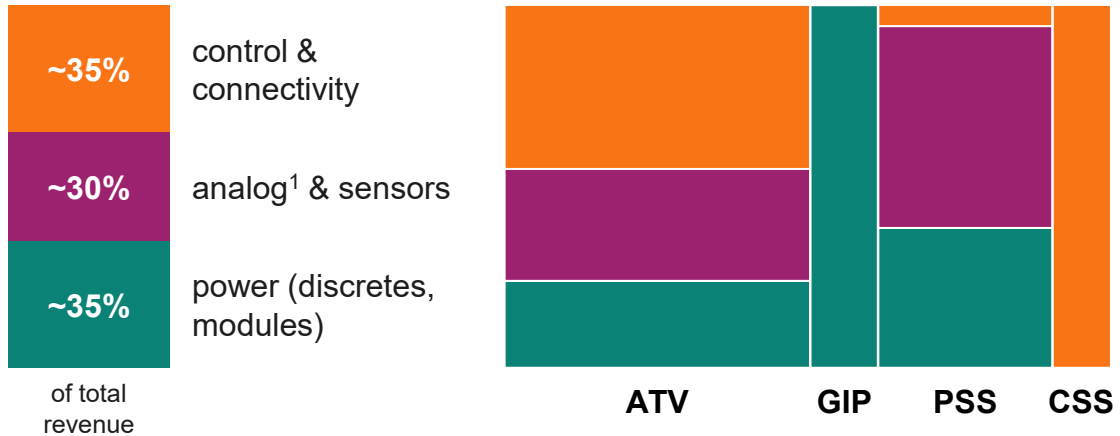
Financials



FY25 revenue by segment



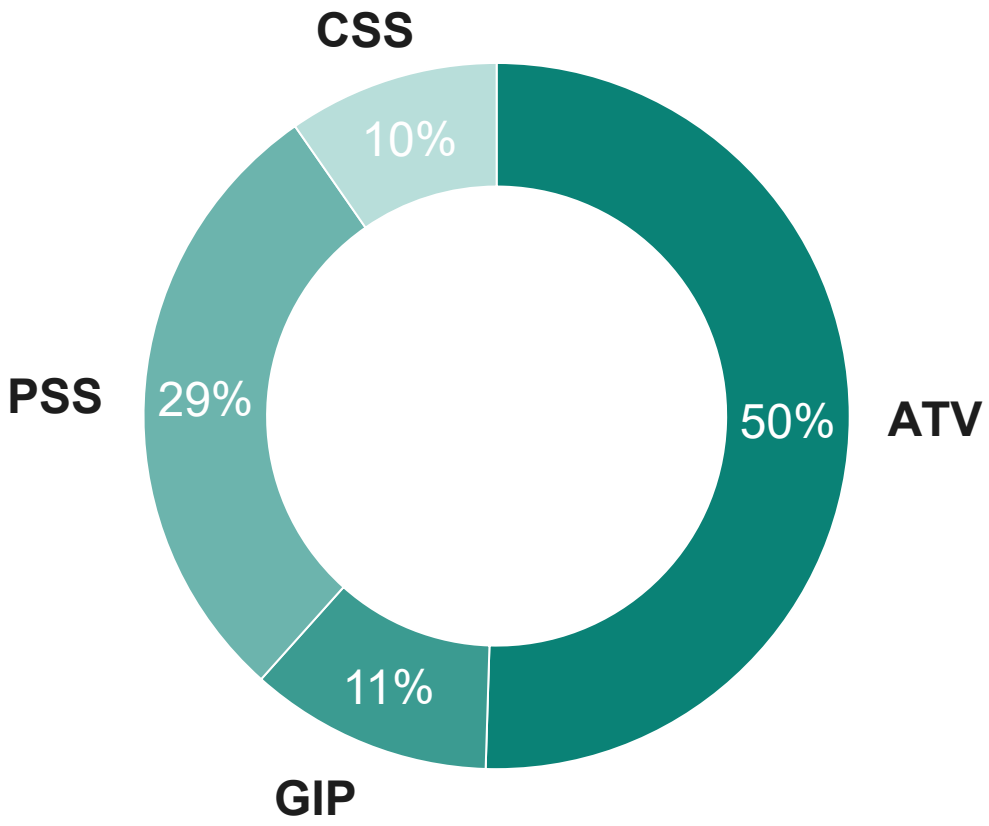
FY25 revenue by product category

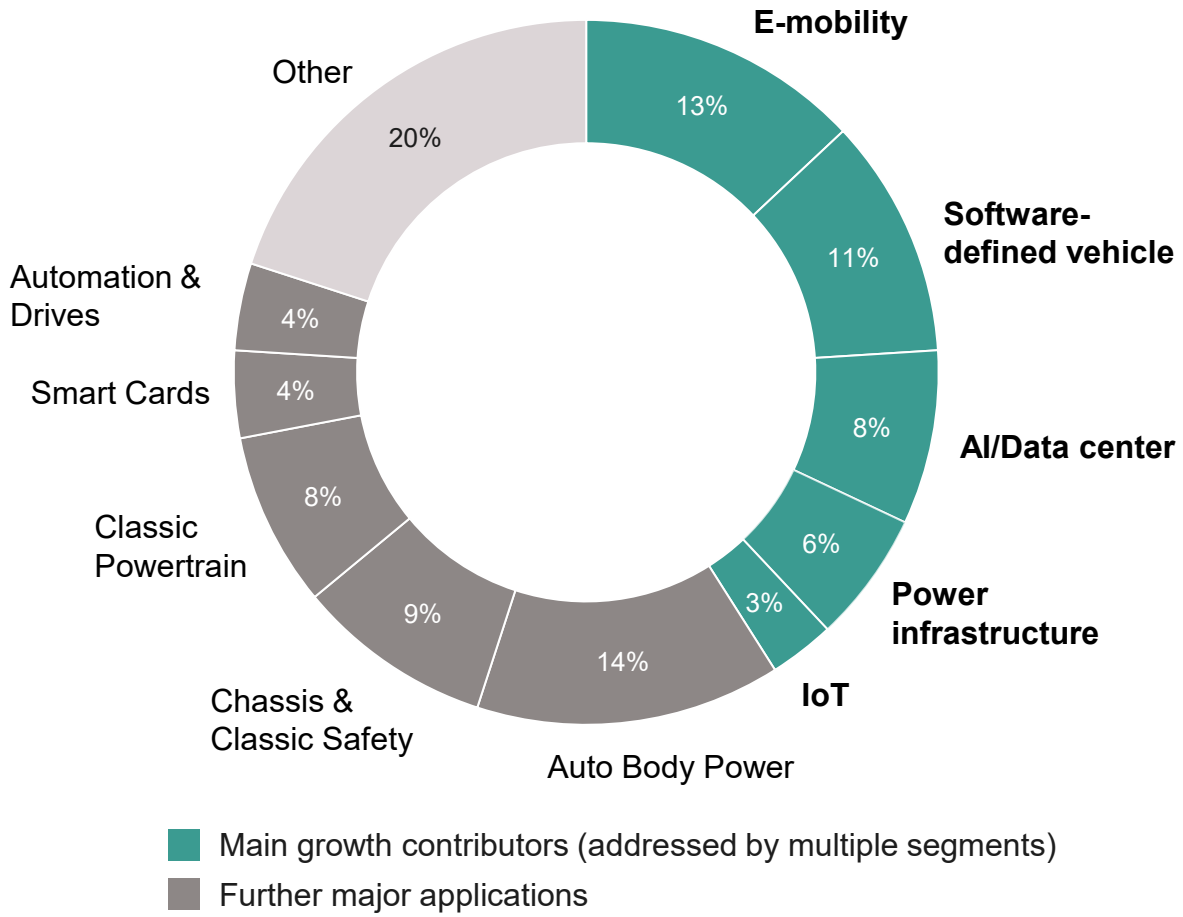


[1] including <5% of differentiating memory technologies

Well-balanced portfolio among segments and key applications, highest growth coming from Decarbonization and Digitalization

FY25 revenue of €14,662m by segment and key application

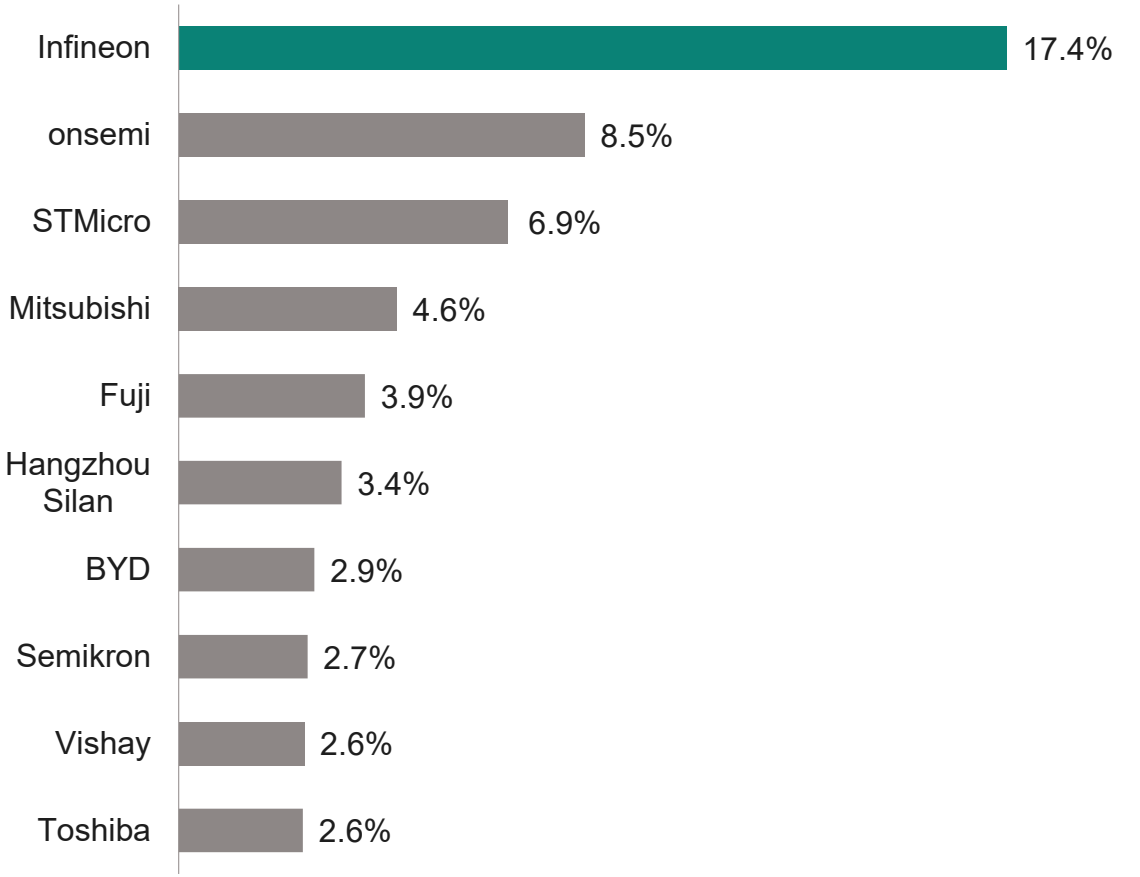




Infineon is a global player, clear #1 in power semiconductors, Automotive semis and automotive microcontroller markets

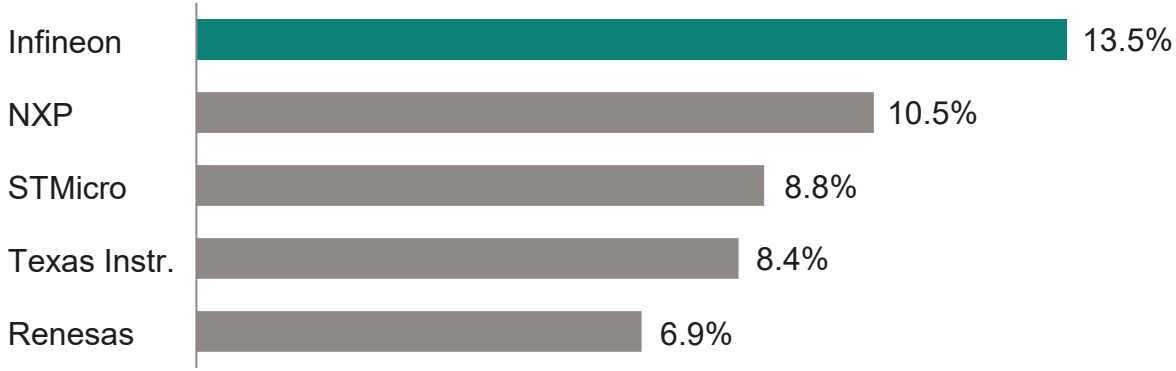
Power discretes and modules

2024 total global market: $32.8bn[1]

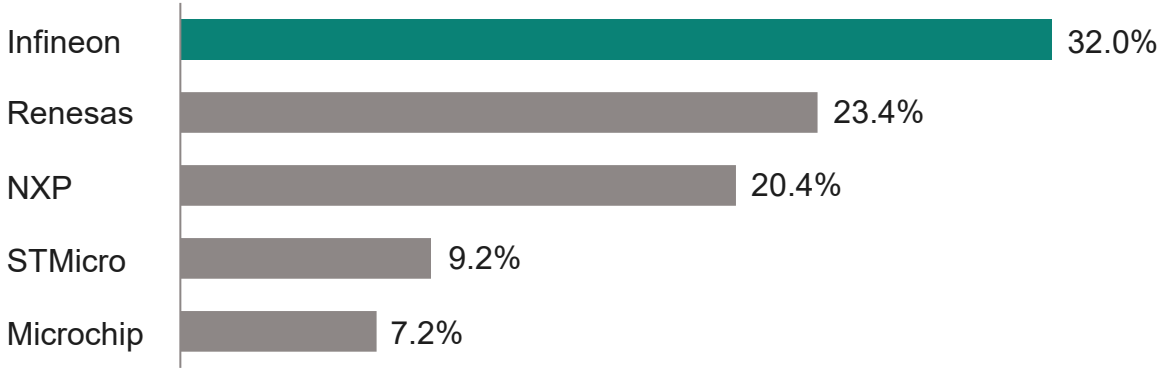


Automotive semiconductors

2024 total market: $68.4bn[2]



Automotive MCUs



[1] Based on or includes research from Omdia: *Power Semiconductor Market Share Database* – 2H25 (2024 Base Year). October 2025. | Results are not an endorsement of Infineon Technologies AG. Any reliance on these results is at the third party's own risk. [2] Based on TechInsights: *Automotive Semiconductor Vendor Market Shares*. March 2025.

Our Target Operating Model: committing to ambitious financial goals and being the sustainability leader

Target Operating Model
through cycle

Revenue growth	**>10%**
Segment Result Margin	**25%**
Adj. Free Cash Flow Margin[1]	**10-15%**

Sustainability leader
CO_2 neutrality 2030

[1] See notes for definition

Modular investment approach for long-term value creation – pull-in of AI related investments for faster ramp

Infineon investments[1] FY26

Strategic investments

– Dresden module 4

Capacity investments

– Smart power and logic: enabling further growth for ”powering AI” and analog/mixed-signal products

– Includes pull-in of €500m to accelerate AI capacity ramp

Research and development

– IFRS capitalization of development cost

Basic investments

– Maintenance, process optimization, quality, IT

[1] Investments are defined as the total amount invested in property, plant and equipment and in other intangible assets, including capitalized development costs

Outlook for Q2 FY26 and FY26

	Outlook Q2 FY26[1]	Outlook FY26[1]
Revenue	~€3.8bn	moderately up vs. prior year
Adj. Gross Margin		low 40s %
Segment Result Margin	mid-to-high-teens %	high-teens %
FCF **Adj. FCF**		~€1.0bn/ ~€1.4bn
Investments		~€2.7bn
D&A		~€2.0bn[2]

[1] Based on an assumed average exchange rate of $1.15 for €1.00
[2] Including the amortization of approximately 400 million Euros from purchase price allocations

Infineon strengthens its sensor leadership with the acquisition of ams OSRAM's non-optical analog/mixed-signal sensor portfolio

analog / mixed-signal sensor business

Strategic rationale

1 Strengthening our global sensor leadership position

- Acquisition of a top European sensor portfolio with complementary products in automotive and industrial end markets
- Expands footprint in high-value medical market

2 Accelerating growth and innovation

- Acceleration of innovation through synergetic R&D
- Acceleration of growth via established Infineon go-to-market channels

Transaction overview

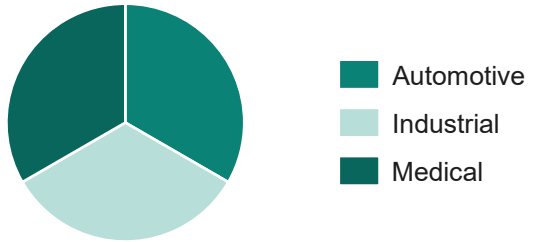
CY26e revenue
~€230 m

Purchase price
€570 m

Employees
~230 employees, thereof ~150 in R&D
fabless asset-deal

Financial impact
EPS accretive from day 1

End market split



A unique opportunity to reinforce our leadership in analog/mixed-signal sensor solutions

Infineon serves all markets with a broad sensor portfolio to provide best solutions in Auto and Industrial

Automotive

- Radar sensors
- Magnetic position sensors
- Magnetic speed sensors
- Magnetic current sensors
- Inductive sensors
- Pressure sensors
- Gas/leakage sensors
- Silicon microphones
- CAPSENSE™ µC

+

- Magnetic position sensors
- Capacitive sensors
- Battery sensors

Industrial

- Radar sensors
- Magnetic position sensors
- Current sensors
- Pressure sensors
- Vibration sensors
- Gas/leakage sensors
- 3D ToF sensors
- CAPSENSE™ µC

+

- Inductive position sensors
- Sensor interface IC
- X-ray sensor IC

Complementing Infineon's leading sensor and sensor IC portfolio across automotive and industrial applications

+

Medical

- Temperature sensors
- Conventional and photon counting IC
- X-ray sensor IC

ams OSRAM analog / mixed-signal sensor business

Expanding our portfolio in medical applications

Compelling financial profile of the transaction

Financial value creation through:

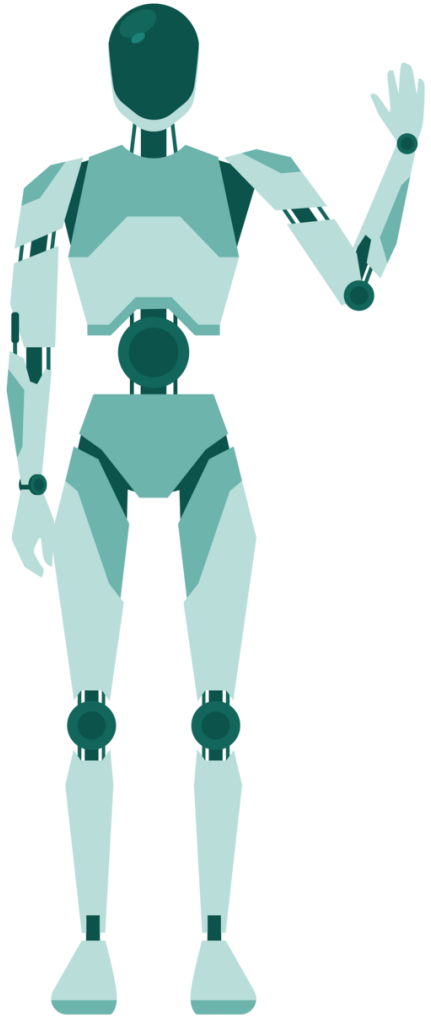
1. Growth and margin profile in line with Infineon TOM
2. EPS accretive from day 1
3. Additional cost synergies within the next 3 years
4. Advanced roadmap leveraging Infineon analog/ mixed-signal products with ams OSRAM's

Transaction outline:

- 570m EUR purchase price, all-cash transaction
- Financed through additional debt
- PMI will follow proven script, integration into PSS Division
- Customary regulatory approvals, closing expected by Q2 calendar year 2026

TOM: Target Operating Model

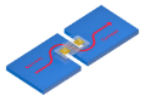
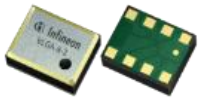
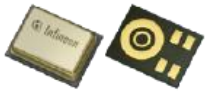
Strengthening of Infineon's leading robotics sensor solutions with acquired portfolio – addressing around 200 sensors



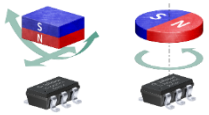
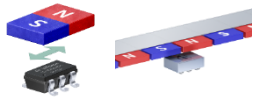
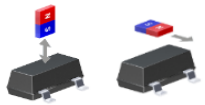
Humanoid sensor usage

- Broad range of **environmental sensors** (pressure, vibration, SiMiC, ToF, radar)
- Capacitive sensing for dexterous hands, **>100 position sensors**, e.g. for joints
- **Current sensors** for battery management

Infineon's current & environmental sensors portfolio

Current sensors	Pressure sensors	Radar systems	Microphones	3D time of flight
				

Infineon's combined position sensor portfolio

3D sensor	Angle sensors	Linear sensors	Magnetic switches	Inductive sensors
				

☐ acquired portfolio

Undisputed power systems leadership mastering all three key materials

- Reliable multi sourcing of raw materials
- World-scale fabs

Controller | **Driver IC** | **Power switch** (Si/SiC/GaN)

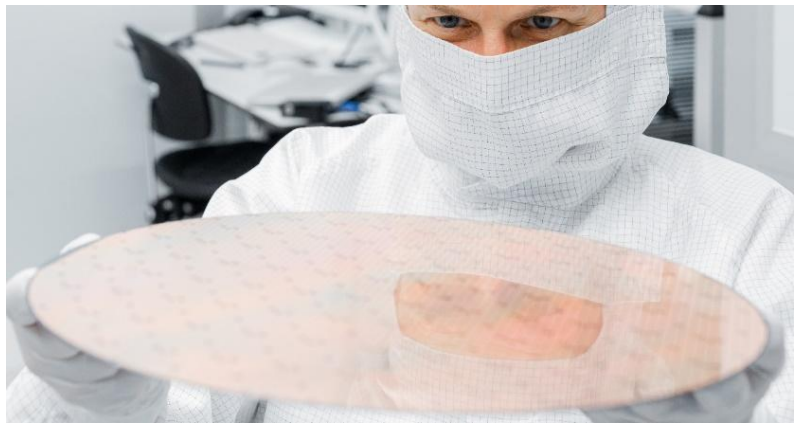
Software + Algorithms

- Application understanding
- Packaging know-how and hybridization competence

Leadership in Power Systems across all materials and technologies

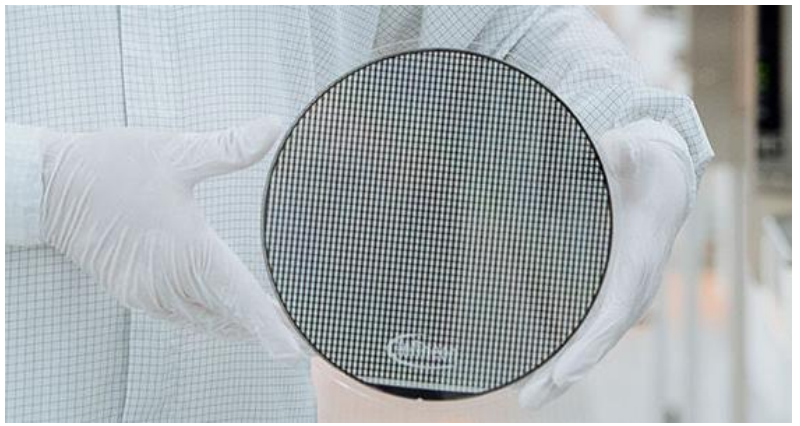
Silicon
Diode – MOSFET – IGBT – Driver – Controller

Si



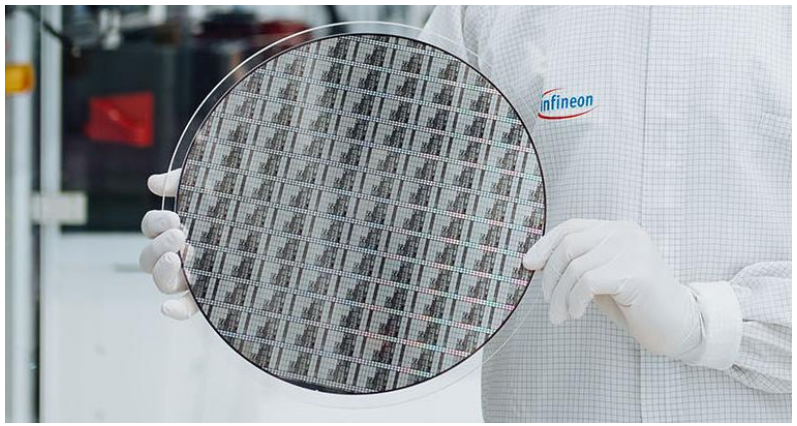
Silicon carbide
Diode – MOSFET

SiC



Gallium nitride
HEMT – Driver

GaN



Infineon is the leader across all power semiconductor technologies – unparalleled portfolio and know-how

Si

World's thinnest silicon power wafer with **20 µm** on **300 mm**

- Broadest Si-power portfolio in the market
- Unmatched quality and leading in all figures of merit (FOM)
- Best price/performance ratio

CoolMOS™ OptiMOS™

SiC

World's most competitive 200 mm silicon carbide power fab

- Broadest portfolio covering auto and industrial applications
- Leading trench performance
- High reliability and robustness in extreme conditions
- Smaller system size

CoolSiC™

GaN

World's first 300 mm gallium nitride power wafer

- Enabling cost parity with silicon
- Highest efficiency at the highest frequency enabling smallest system size
- Allow functional integration

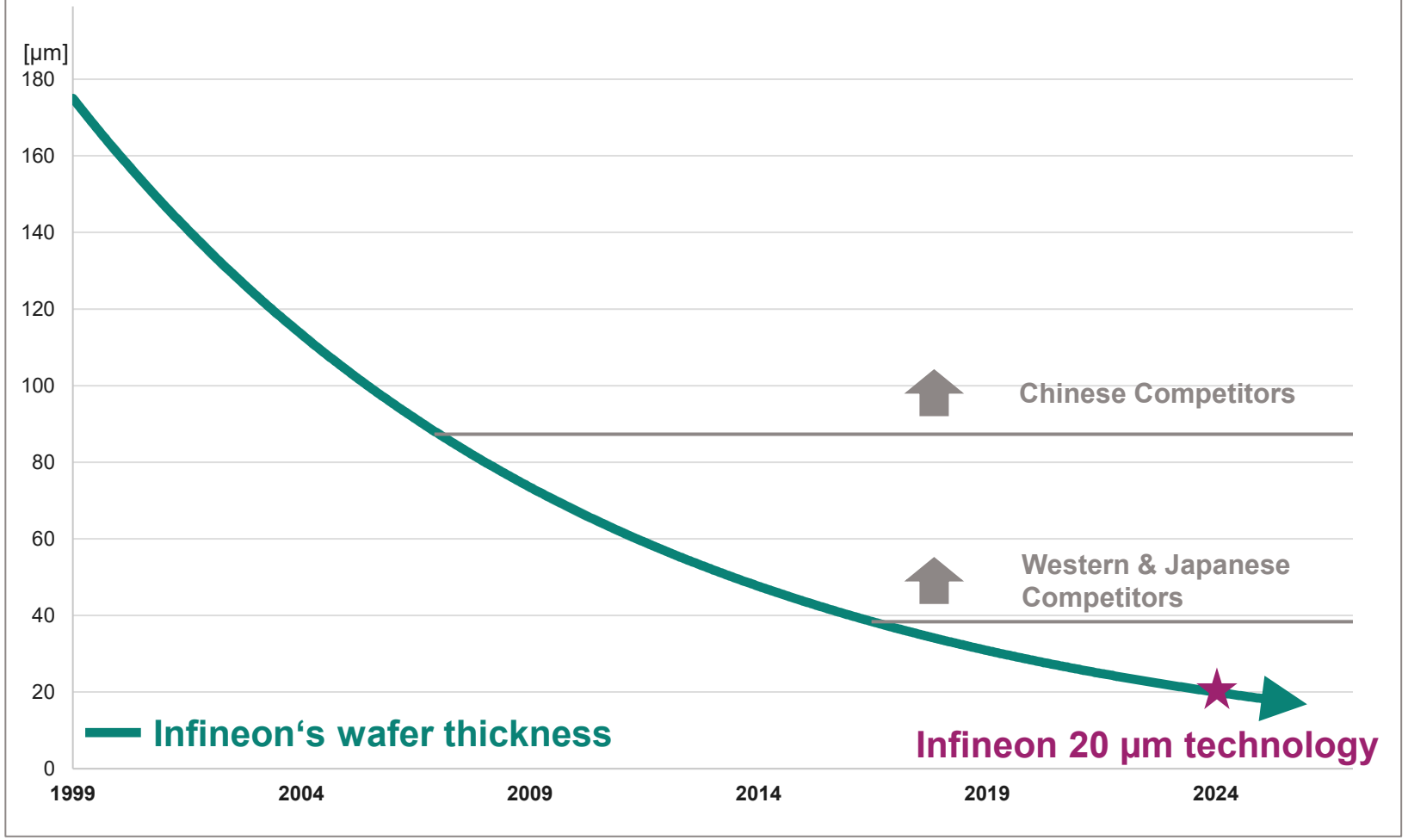
CoolGaN™

Infineon is strengthening its position as the industry's innovation leader leading the way in all three power semiconductor materials

Infineon presents the world's thinnest silicon power wafer paving the way for more energy efficient power systems

Si

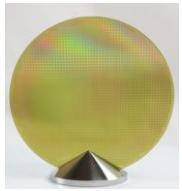
Infineon reduces wafer thickness from 40 µm to 20 µm



- Infineon pioneers 20 µm process at high-scale production
- Halving thickness also halves resistance, reducing power loss by >15%
- Enables easy and robust signal routing from front to backside
- Technology qualified by customers and applied in Infineon's Integrated Smart Power Stages for DC-DC converter in AI servers

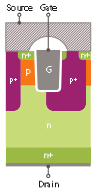
With Kulim 3, Infineon is on track to becoming the industry's most competitive provider of SiC technology

SiC



SiC raw material supplier network

- More than 6 qualified SiC wafer and boule suppliers
- Globally diversified and resilient



Superior trench technology

- 30% more chips per wafer than planar
- Unmatched reliability with zero field returns

Packaging portfolio

- Best-in-class in-house packaging solutions
- .XT technology for highest power density

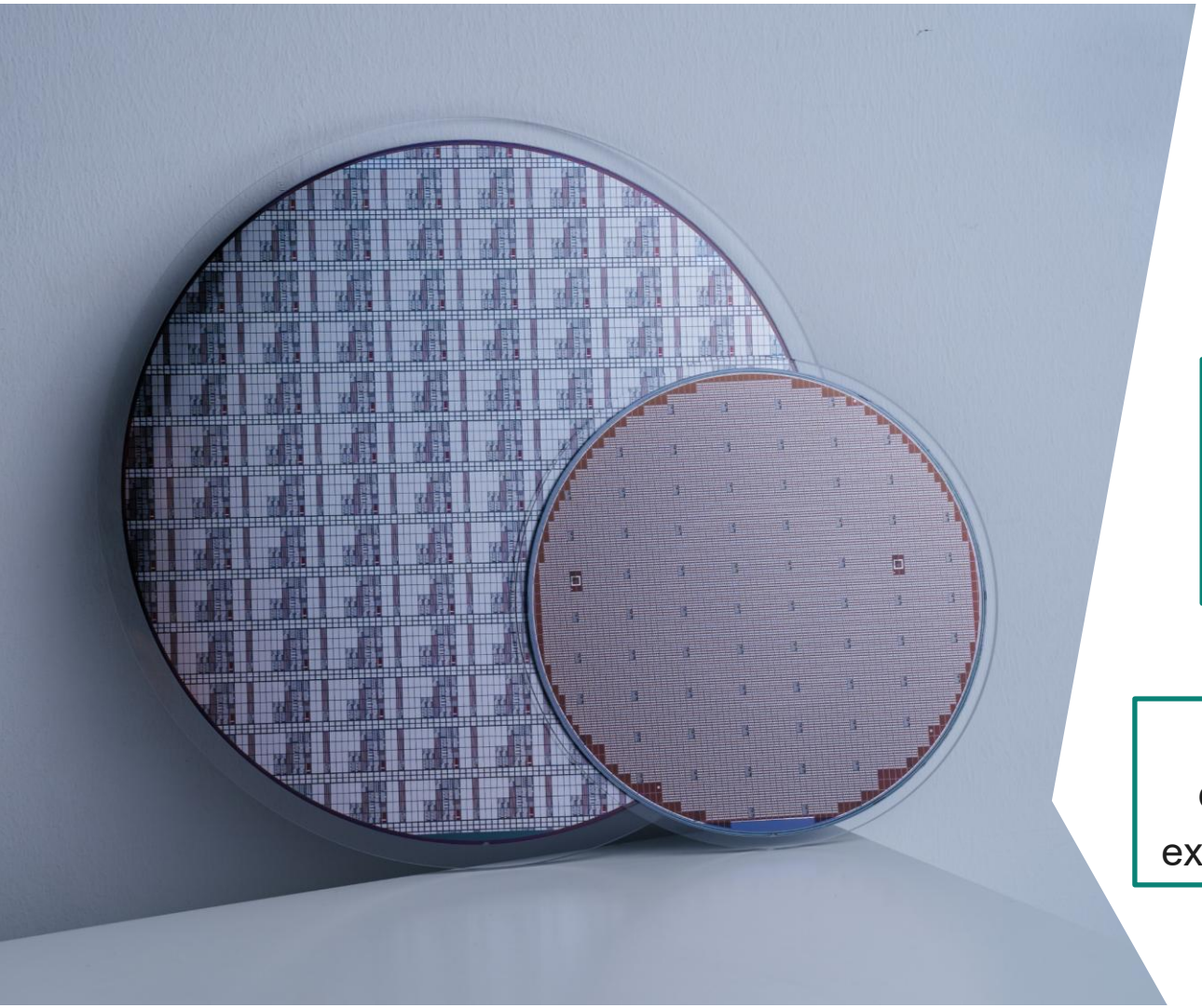
P2S

Deep system understanding

- Decades of experience
- Broadest portfolio: off-the-shelf plus customized solutions

Most competitive 200 mm fab with industry-leading cost position.
Resilient setup together with Villach plant

Infineon is a leader in GaN technology and can build on the industry's broadest IP portfolio and application expertise



Broadest IP portfolio in the market (~350 patent families)

Leading GaN product portfolio MV and HV applications

World's first 300 mm GaN manufacturing process strengthens cost-effectiveness

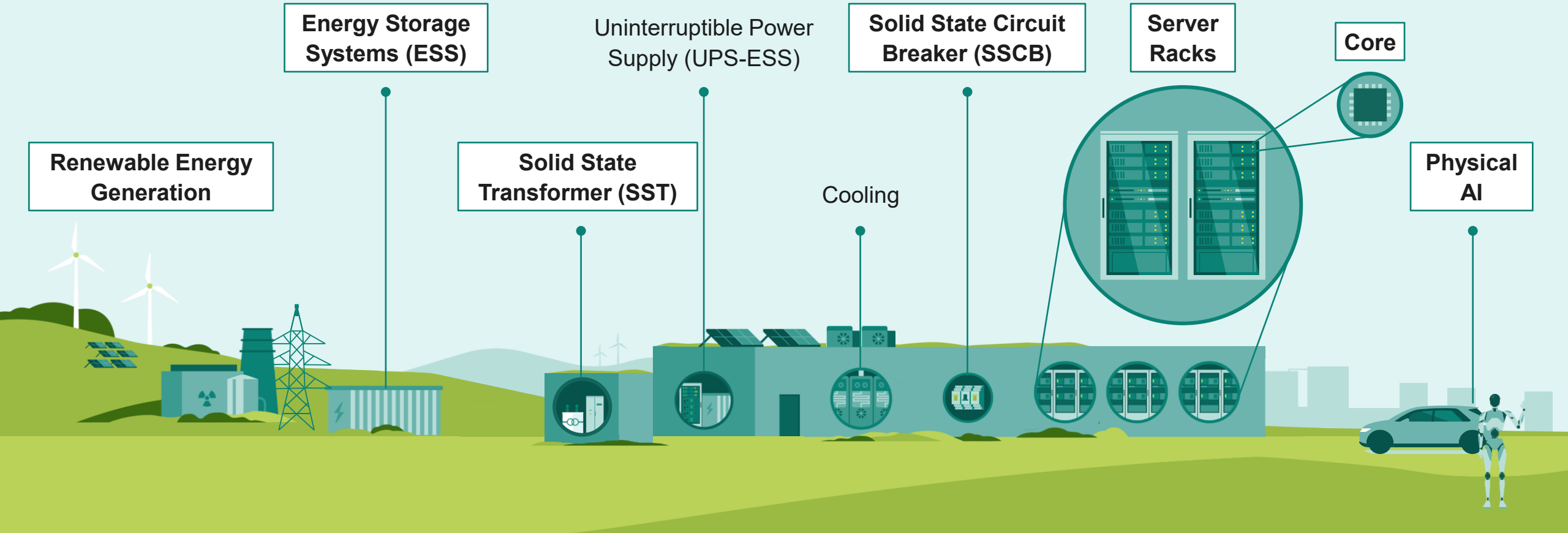
Leadership in GaN

Proven application expertise with > 400 GaN experts and system know-how

Superior customer supply stability through dual-sourcing and scalability

Infineon products are essential for AI power supply and secure operation of data centers – from grid to core and beyond

Grid | Rack | Core | Physical AI



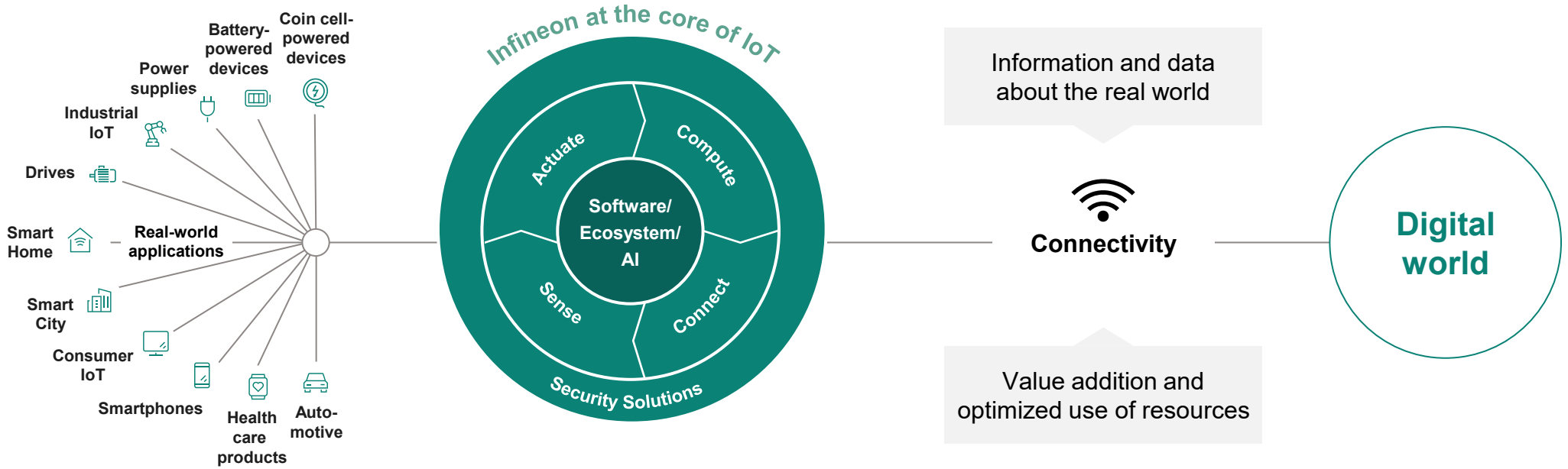
Infineon at the core of IoT – driving digitalization by serving strongly growing multi-application markets

Consumer IoT

Industrial IoT

Automotive IoT

Products: MCU – Connectivity (Wi-Fi, BLE, NFC) – Sensors – Security – Power supply & switches



ESG:
Targets and achievements

Important milestone achieved: The Science Based Targets initiative (SBTi) has approved our CO_2 emission reduction targets

SBTi validation of Infineon's 2030 CO2 reduction targets marks a major step in our decarbonization journey

- **Scope 1 and 2 targets align with the Paris Agreement, limiting global warming to 1.5°C**
  Specifically, Infineon has committed towards SBTi to **reduce** absolute Scope 1 and 2 greenhouse gas (GHG) emissions by 72.5% by 2030 versus the base year 2019.
- **New Scope 3 commitment**: 72.5% of supplier emissions to be covered by science-based targets by 2029.
- **Key reduction measures** include green electricity, energy efficiency, and voluntary GHG abatement.
- Infineon remains **committed to 100% CO_2 neutrality** goal in Scope 1 and 2 by 2030, as announced back in 2020
  This will include compensation for the smaller part that cannot be reduced

Our 2030 carbon neutrality goal is aligned with the Paris Climate Agreement's 1.5°C target

CO_2 burden[1]

2.7 million tons of CO_2 equivalents

Ratio

~1:53

previously 1:45

CO_2 savings[2]

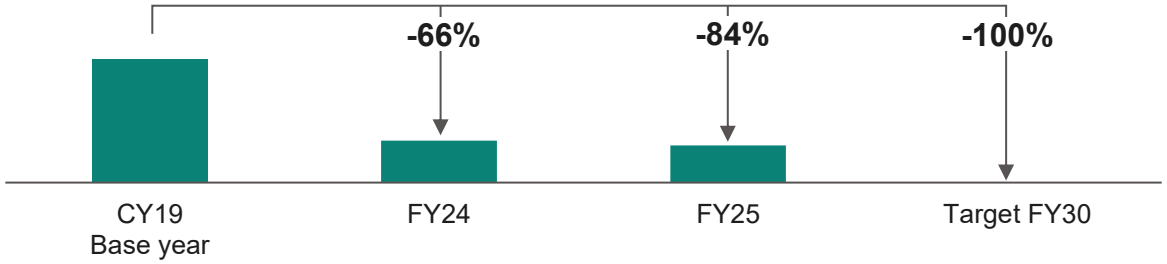
143 million tons of CO_2 equivalents

On the road to carbon neutrality[3] we achieved significant milestones

- Overachievement of our 70% reduction target for FY2025
- Usage of green electricity in all our sites

Infineon's CO_2 target[3] by 2025 and 2030

Net CO_2 emissions in million tons of CO_2 equivalents



Net ecological benefit: **CO_2 emissions reduction of more than 140 million tons**

[1, 2, 3] For further explanation see "ESG footnotes" in the appendix

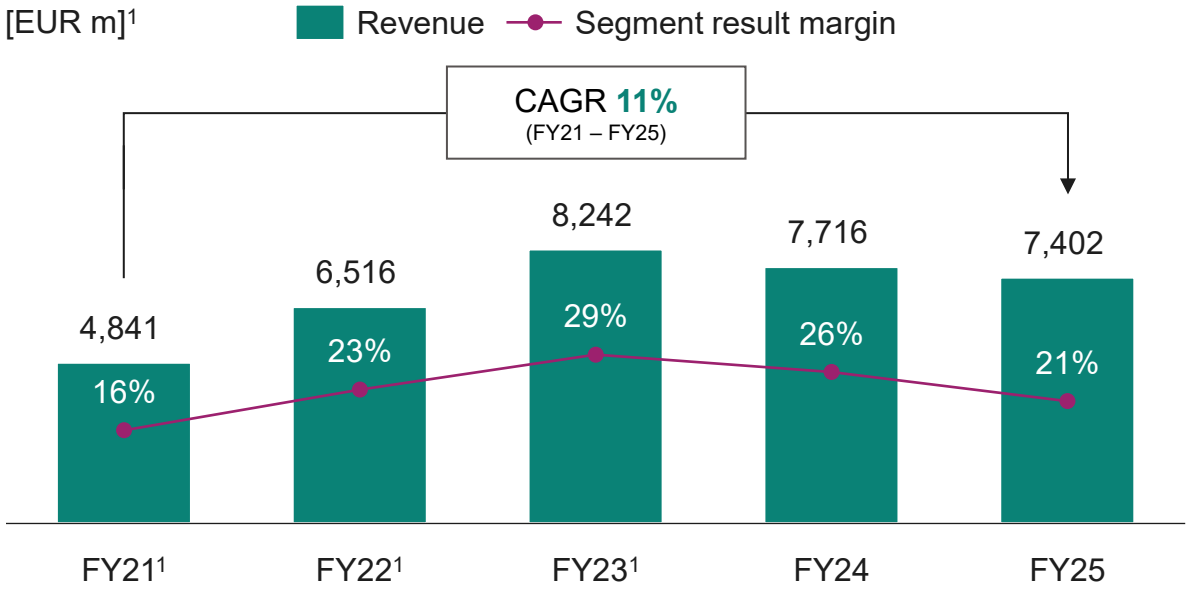
External recognitions confirm our engagement in contributing to a sustainable society

	Rating/Score	Scale	Date
MSCI ESG	AAA	CCC to AAA	05/2025
CDP	B climate scoring B water scoring	F to A	01/2026
Ecovadis	99th percentile “Platinum” award	0 to 100	09/2025
Dow Jones Sustainability™ Index	Dow Jones Sustainability™ World Index listing	-	12/2024
ISS ESG Corporate Rating	Prime Status	-	03/2025
FTSE4Good Index	Index member	-	07/2025
Sustainalytics	ESG industry top performer	-	01/2025

Automotive

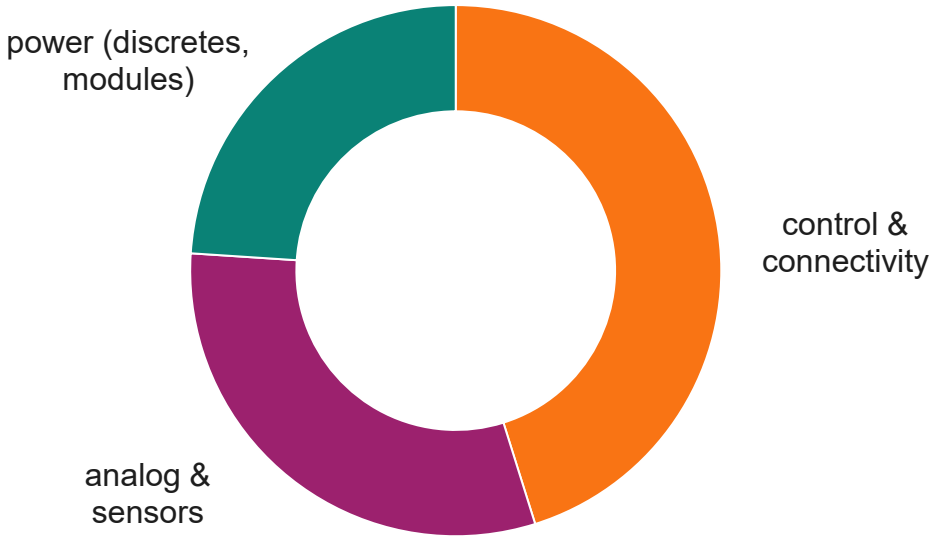
ATV at a glance

ATV revenue and segment result margin



[1] Transfer of "Sense & Control" business line from ATV to PSS from 1 January 2025 onwards not reflected in prior year numbers

FY25 revenue split by product group

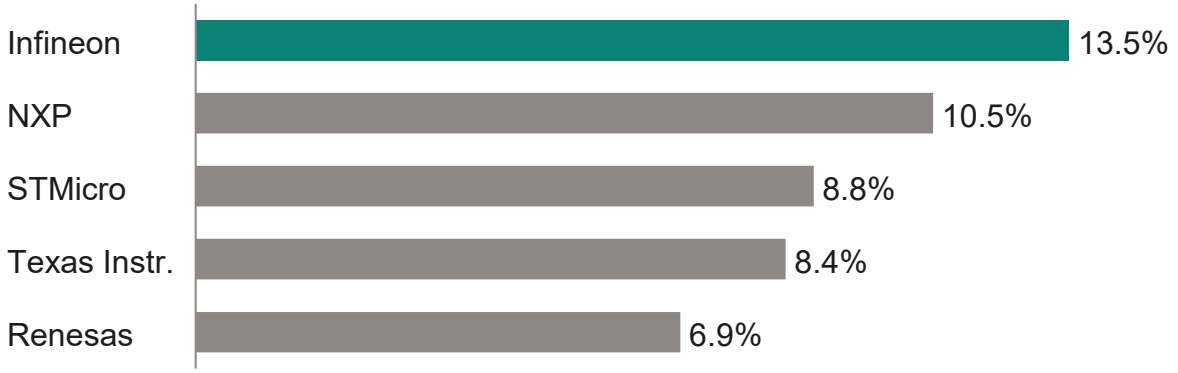


Key customers

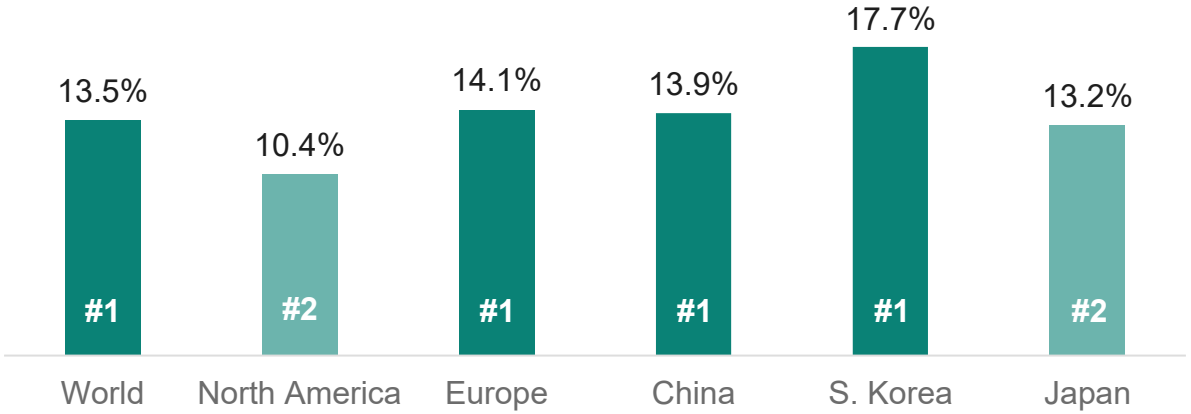
APTIV · Astemo · AUMOVIO · BorgWarner · BOSCH · BYD · DENSO · FORVIA
HYUNDAI MOTOR GROUP · KEBODA · Mando · MAGNA · SCHAEFFLER · Valeo · veoneer · ZF

Infineon's top market position is built on system competence based on an industry-leading product portfolio

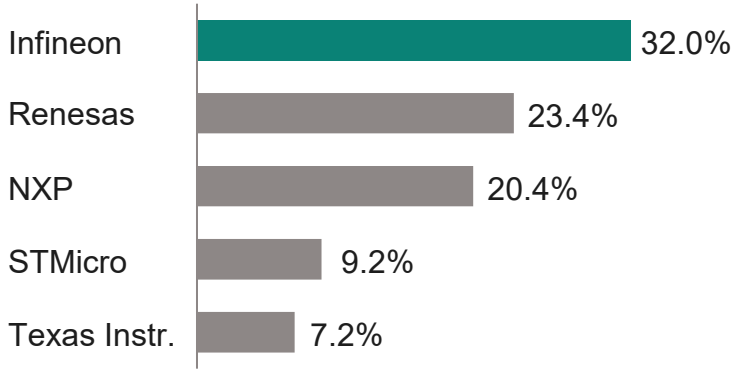
Automotive semiconductors (2024 total market: $68,382m; -1.2% y-y)



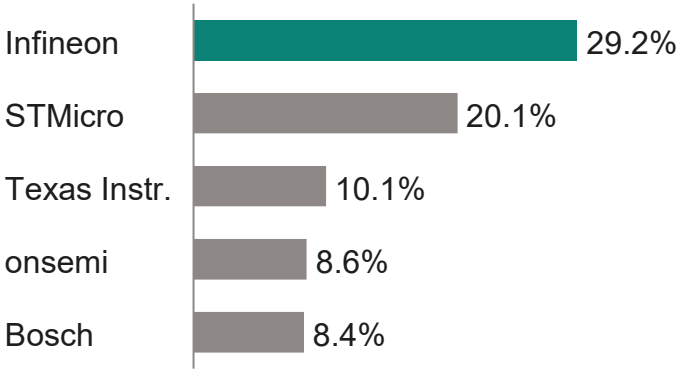
Infineon's 2024 market share and position by region



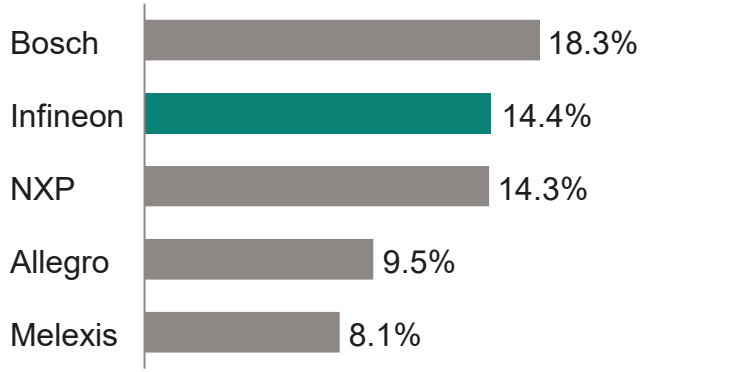
MCUs



Power semiconductors



Sensors



TechInsights: *Automotive Semiconductor Vendor Market Shares*. March 2025. Sensors: S&P Global Mobility: *Automotive Semiconductor Market Share Database.* May 2025.

Several strong content growth drivers for Infineon in xEV and software-defined vehicles, even at flat LV production

Structural trends fueling our growth

xEV

- Strong volume growth of BEVs and PHEVs
- Increasing share of SiC in traction inverters
- More kW per vehicle lead to higher BoM in inverter

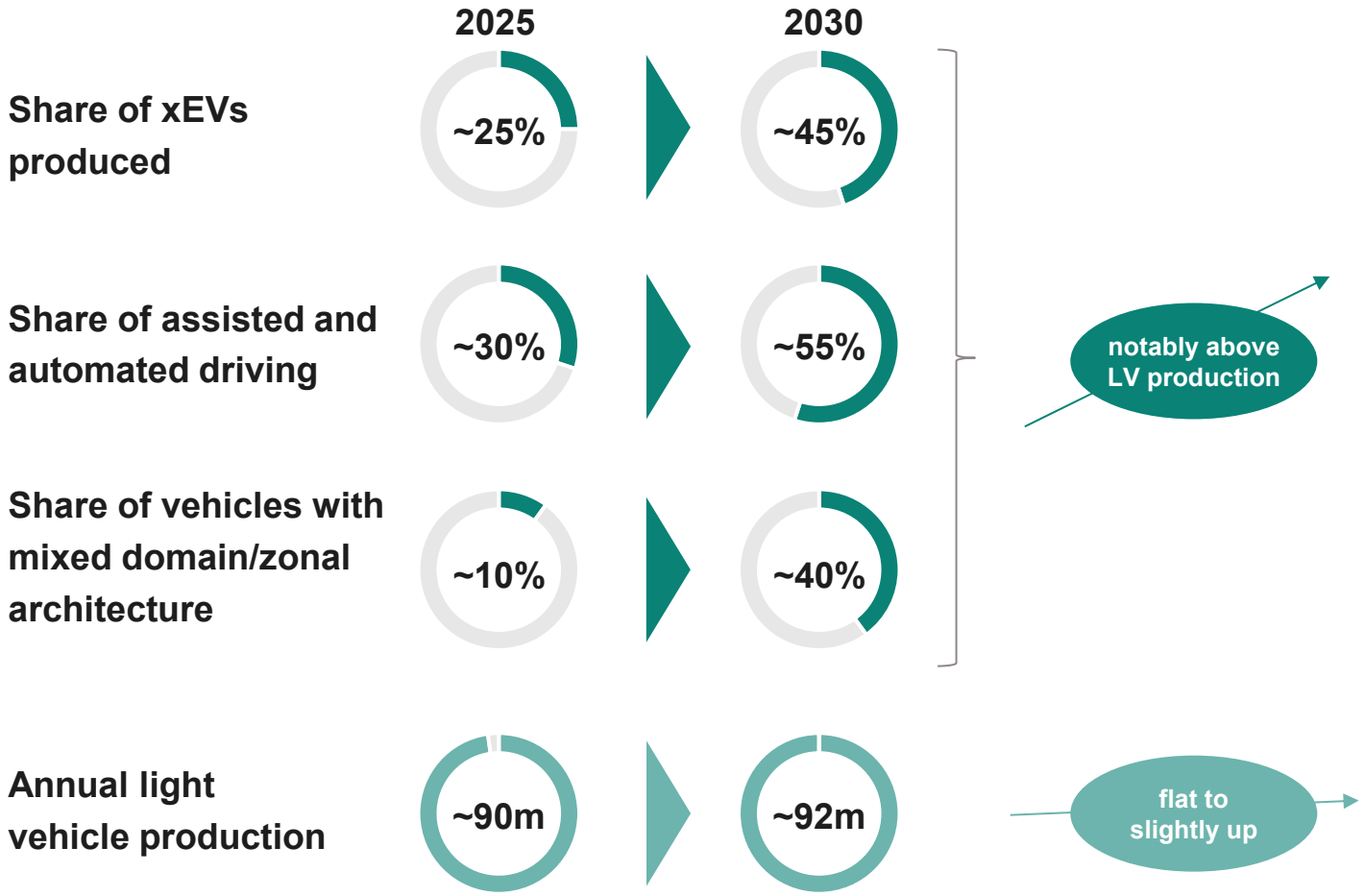
SDV

- Transformation of E/E architecture towards central computing with zonal controllers
- Smart switches for decentralized power distribution
- Software over the air
- Secure connectivity, cybersecurity indispensable
- Functional safety, dependable electronics, redundancy
- ADAS/AD: More sensors, more computing performance

Comfort and premium features

- More loads (motors, heating, cooling etc.)
- More elaborate lighting, both exterior (matrix light) and interior (instruments and ceiling)

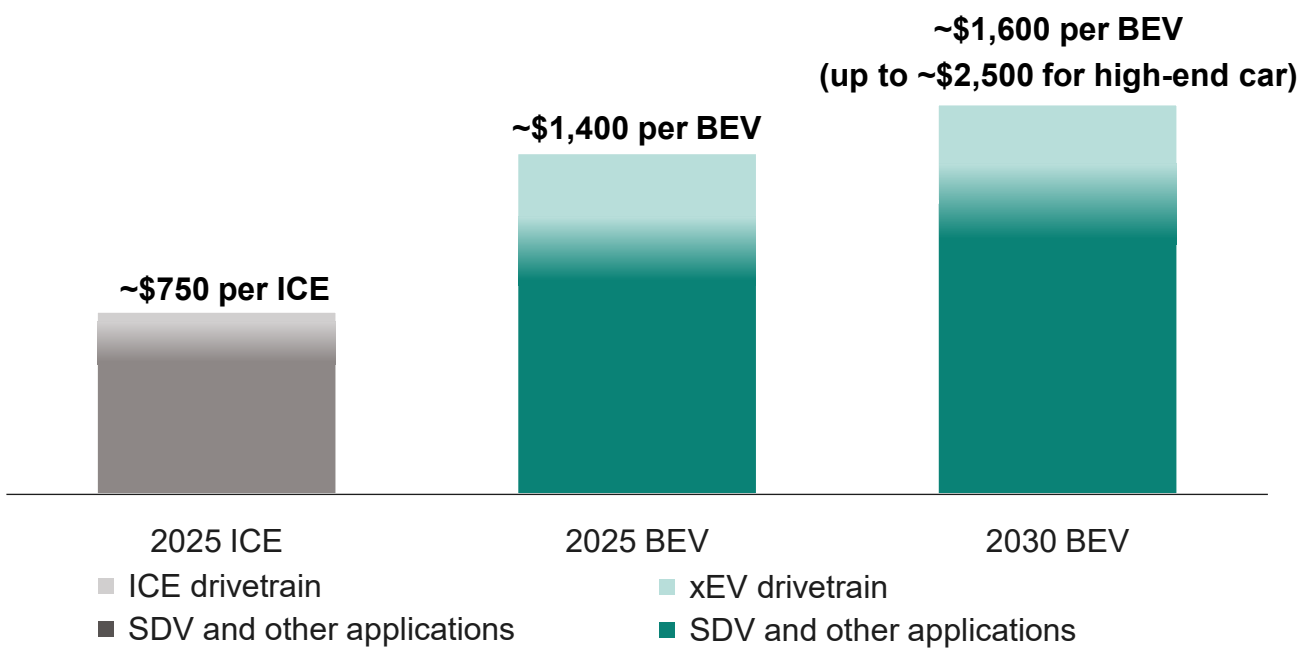
Overview of growth vectors until 2030



Infineon estimates

Infineon is the world leader in automotive semis, serving all key applications and benefiting strongly from content growth

Average semiconductor bill-of-material per car in 2025 and 2030



BEV market size growth (vehicle production)

Semiconductors covered by Infineon

Drivetrain applications:

- Traction inverter, OBC, DC-DC, BMS, auxiliaries
- Drivers for BoM increase:
  - SiC and GaN replacing Si
  - more motors and stronger motors per car
    → slight increase in kW per car

SDV and other non-drivetrain applications:

- Domain/Zone
- SDV, incl. E/E architecture and ADAS
- Safety and advanced security
- Comfort and premium
- Connectivity and infotainment

With a growing xEV market and growing non-drivetrain BoM, Infineon profits twice

Infineon estimate based on S&P E/E & Semiconductor Service dataset – October 2025; November 2025

Number of power MOSFETs per car continues to increase, and drives accelerated growth for the leading portfolio

Examples of MOSFET applications

Power door
Power lift gate
Brake booster
Electric power steering
HV-LV DC-DC conversion
BMS
Transmission control
Windshield wiper
Electric parking brake
HVAC blower
Sunroof
Side mirror
Seat adjustment
Thermal management
12 V battery switch
Power supply protection

Latest portfolio with constant innovation

Technologies, packages and voltages

OptiMOS™ 7
OptiMOS™ 6
OptiMOS™ 5
OptiMOS™ T, T2, Gen 12.7

40 V
60 V
80 V
100 V
120 V

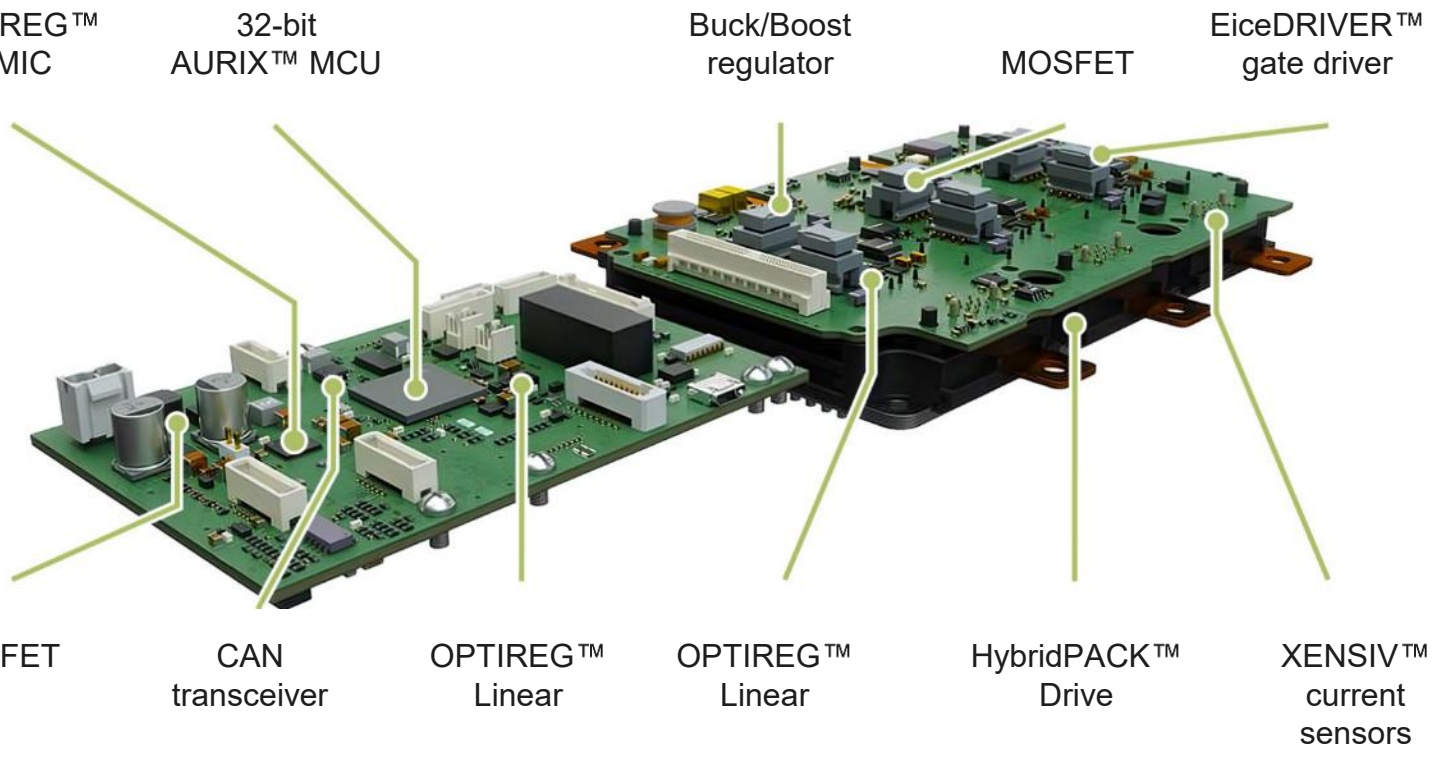
New **OptiMOS™ 7** family with outstanding technical performance

- 100 to 180 MOSFETs are used per vehicle in ~90 different applications in all segments: body, chassis, safety, ADAS/AD, powertrain
- Infineon offers broadest portfolio (>600 products) and eco-system to address specific and high-margin applications:
  - embedded control, gate driver, MOSFETs, software, P2S
  - entire eco-system with digital twins
  - simulation environment (esp. for motor control)

Electromobility

Infineon’s broad product portfolio and system understanding enable higher BoM and allow compact designs and fast T2M

Infineon inverter reference design, covering up to 95% of value



P2S (product-to-system approach)

- Reference design for up to 300 kW, further customization possible
- System solution for easy implementation
- Fast time-to-market (T2M)

Freedom of choice

- IGBT and SiC in 750/1,200 V scale up to preferred power class
- HybridPACK™ Drive CoolSiC™ Gen2 continuous operation at 175°C
- EiceDRIVER™ gate driver Gen3 optimized for CoolSiC™
- Optimized 32-bit AURIX™ MCU

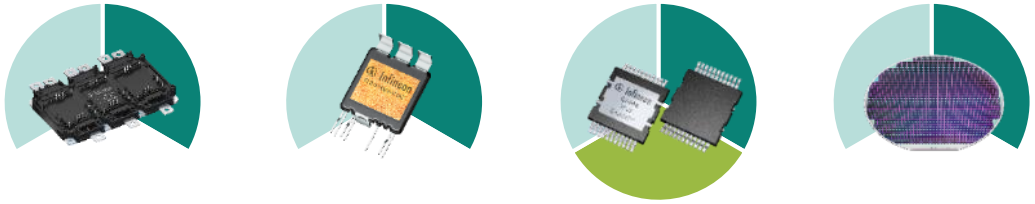
Competitive setup, unmatched portfolio breadth and our worldwide customer base lead to accelerated growth in SiC

Leading SiC technology and production efficiency

- Unrivaled productivity with most competitive fab and most diversified supplier network
- Superior trench technology and highest reliability
- Extensive packaging portfolio and complete system competence

Most scalable SiC auto portfolio

650 V | 750 V | 1,200 V



Module | DSC/SSC module | Discrete | Bare die

Continued strong SiC design-win momentum

BMW, BOSCH, 长安汽车 CHANGAN, CHERY, CHRYSLER, DELTA, FIAT, GENESIS, HYUNDAI, INOVANCE Automotive, JOHN DEERE, KIA, LEAPMOTOR, LI AUTO, RAM, RIVIAN, SAIC, SCHAEFFLER, smart, STELLANTIS, TOYOTA INDUSTRIES GROUP, Valeo, VINFAST, VW, Xiaomi, XPENG, ZF

Infineon AURIX™ TC4x with integrated PPU brings AI-on-the-edge to the battery

- **Battery cost**
- **Battery health**
- **Charging speed**
- **Safety concerns**
- **Range anxiety**
- **Resale value, residual value**
- **Cloud dependencies (latency, cost, stability)**

AURIX™ TC4x

PPU
(parallel processing unit)

High computing performance with complex and accurate BMS algorithms

- AI-based battery diagnostic on-the-edge
- temperature model, electro-chemical model
- lithium plating detection
- remaining useful life prediction
- with and without cloud-based updates
- Product-to-System!

Efficient battery cell utilization
- Higher capacity
- Less cells
- Lower battery cost

Faster charging
- Higher user experience

Assure longevity, extended guarantee
- Longer lifetime (in years, in km)
- More charging cycles

Detect and prevent thermal runaway

Accurate battery, health prediction

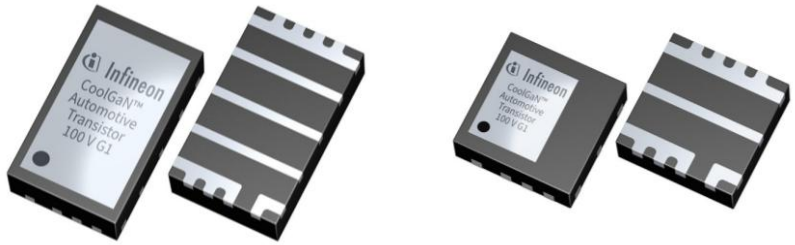
Trust in resale market
- Higher economic value (impacting insurances, fleets, OEMs, Tier1s, 2nd life market)

Open to partner up with further OEMs, Tier1s, insurance companies

Infineon strengthens its leading position in automotive semis – introducing the CoolGaN™ automotive transistor 100 V G1 family

CoolGaN™ automotive transistor 100 V G1 family

- First GaN transistor family qualified to AEC-Q101 for automotive applications
- Features CoolGaN™ transistors and bidirectional switches
- Enables higher energy efficiency and lower system cost
- Combines smaller form factor with higher power density
- Ideal for zone control, main DC-DC converters, high-performance auxiliary systems, and Class D audio amplifiers



Main automotive target applications and the benefits of GaN

On-board charger

HV/LV DC-DC

Higher efficiency: energy savings

Higher power density: less material & smaller size

Lower system cost: more affordable

Traction inverter

48 V/12 V DC-DC

GaN supports new inverter topologies

Efficiency gain (more range or smaller battery)

Power conversion for E/E architecture

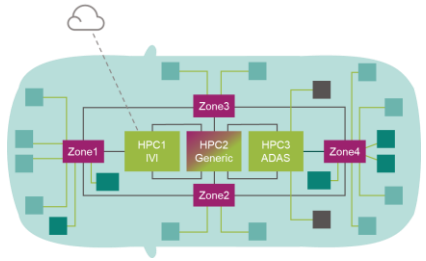
Less material, smaller size, and lower system cost

Software-defined vehicle

Software-defined vehicles are enabled by safe/secure computing, high-speed in-vehicle networks, and intelligent power distribution

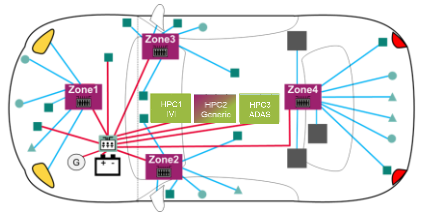
Advantages of software-defined vehicles

- **standardization** of components
- new features in **safety and security**
- **reduced complexity** and **cost** of wire harness
- monetization of **functions & data**
- new features in **comfort**, **connectivity** and **infotainment**
- **digital lifecycle** management



Safe and secure computing and high-speed in-vehicle network

- Evolution to hierarchical/centralized
- Application software decoupled from hardware
- Management of real-time communication in each zone
- **Automotive Ethernet as key differentiator**



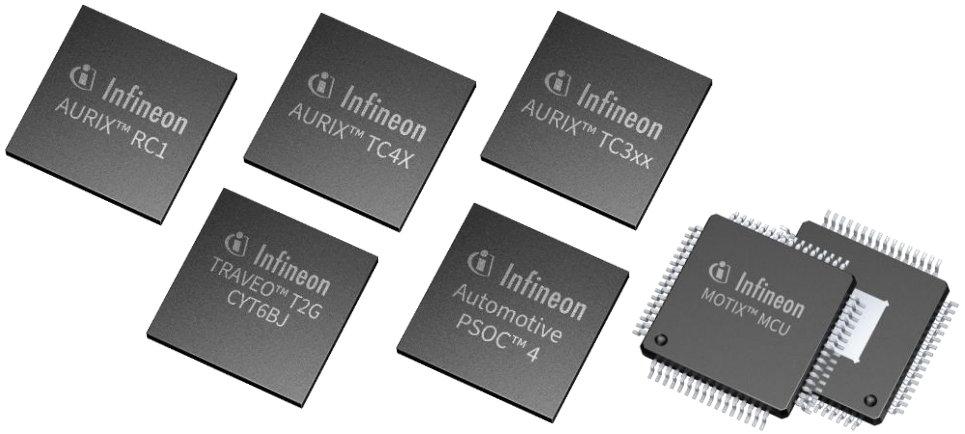
Intelligent power distribution

- Evolution from centralized to decentralized
- Power distribution safety element for
  - freedom from interference
  - system availability up to ASIL-C for ADAS
  - fail-operational of ASIL-D for AD and x-by-wire

The Automotive Ethernet portfolio strengthens our market leading MCU position and increases offering for zonal architectures

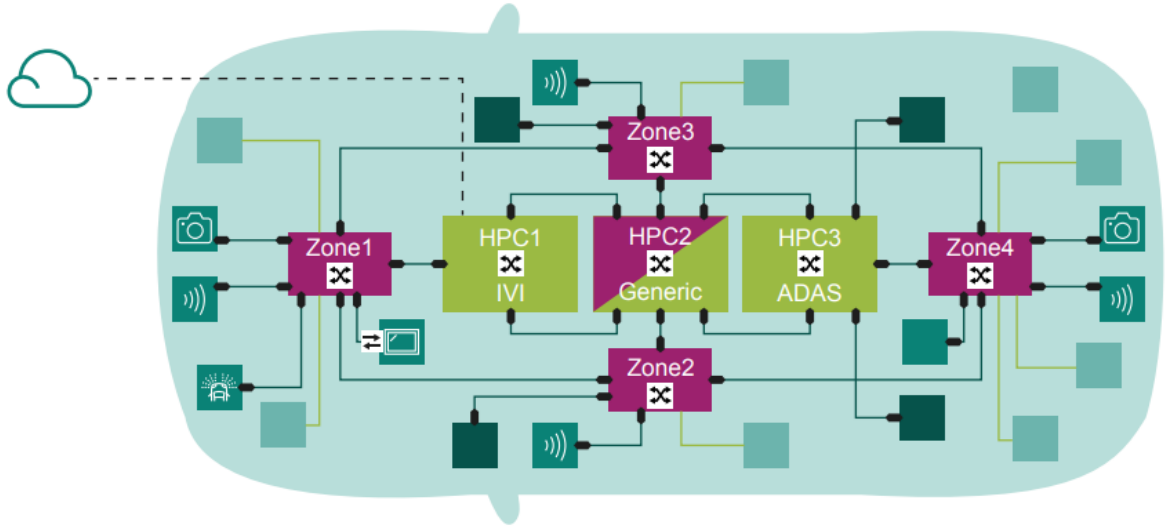
Infineon's unique portfolio of MCU and Ethernet

Automotive MCUs



Automotive Ethernet

Components of hierarchical E/E architectures:



High Performance Computing (HPC)

Complex sensors & actuators

Simple sensors & actuators

Zone controller

Control ECU

Scope of Acquisition

PHY

Bridge

Switch

Ethernet

Low-bandwidth network

Infineon's extended portfolio contributes essentially to SDV as the second growth pillar alongside e-mobility

Infineon components for hierarchal computing E/E architecture

Infineon BoM potent.: ~$500

HPC

SoC/MPU, Safety Comp., Smart Power, Gate Driver, MOSFET, Switch
MPC[1], PMIC, Memory, Vreg, LIN/CAN Tx, PHY

- High-level control for complex, safe and secured driving functions
- High-bandwidth communication

1-3 units per car
~$45 each

Zone

MCU, Smart Power, Gate Driver, MOSFET, Switch
PMIC, Memory, Vreg, LIN/CAN Tx, PHY

- High-performance real-time control
- I/O aggregation
- Low-latency protocol handling

2-5 units per car
~$50 each

Edge Compute

MCU, Smart Power, Gate Driver, Switch
PMIC, Vreg, MOSFET, PHY

- Low-/medium-performance real-time control
- End-point communication interface
- Direct connection to sensors and actuators
- Sensor data collection and pre-processing

10-20 units per car
~$15 each

Total BoM for Infineon increases by almost $100 due to Ethernet

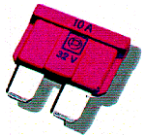
[1] Digital multi-phase controller for SoC/MPU

Control, Analog, Memory, Power, Ethernet, Component if needed, Not part of Infineon portfolio

Smart semiconductors in power distribution systems are key enabler for SDV while ensuring high availability and resilience

Infineon PROFET™ Wire Guard enables SDV

Relay replacement



Fuse replacement

Load status diagnostics

Switch

Protect

Diagnose

e.g. PROFET™ Wire Guard

PRO SIL **ISO 26262 compliant**

Fast failure isolation
(< 500 µs)

Central fuse box + many individual ECUs

- Big and heavy
- Complex wire harness
- High power loss
- Risk of interference

Decentral zone ECUs

- Light and small
- Simplified wire harness
- Power efficient
- Freedom from interference
- Design flexibility
- Enable ADAS/AD, x-by-wire

48 V enables higher power demand features for future E/E architectures and automated driving

Demand of in-vehicle loads is sharply increasing and requires 48 V architectures

- More high-power applications and the introduction of zonal E/E architectures drive the need for higher power capabilities
- 12 V power systems are facing challenges
- Future-readiness for automated driving

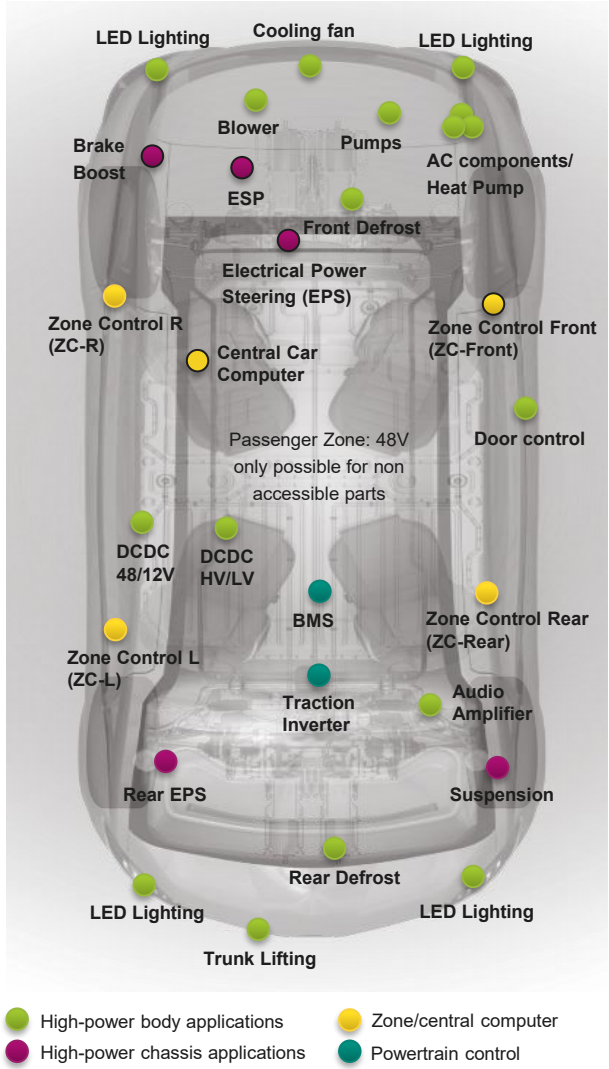
Present high-power features

– Body control	~1 kW
– Chassis control	~1 kW
– Powertrain control	~1 kW
– Cockpit and ADAS control	~0.5 kW
Power demand	**3-4 kW**

around 3x

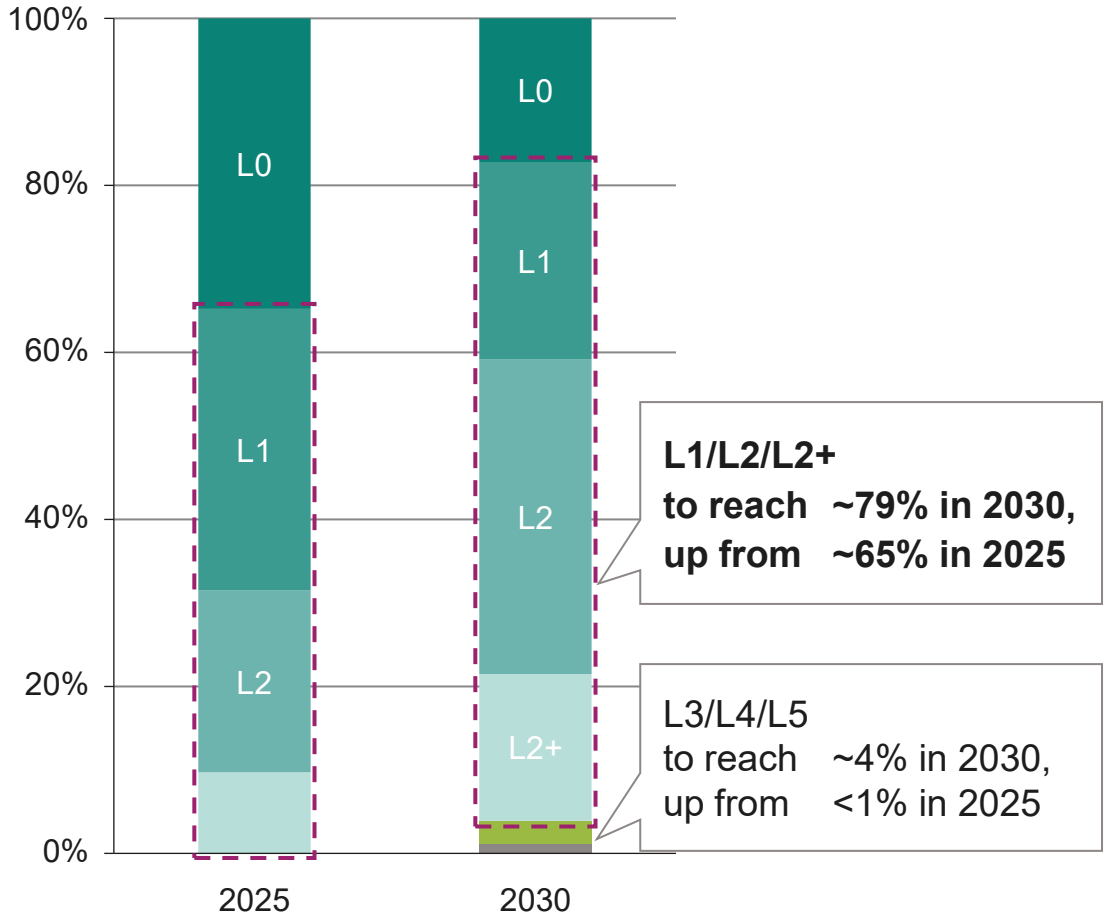
Future high-power features

– Steer-by-wire (EPS)	1-2 kW
– Rear wheel steering	1-1.5 kW
– Brake-by-wire (electro-mechanical brake)	1-2 kW
– Active roll control	~3 kW
– Active suspension	2-3 kW
– Central computer	1-3 kW
– Cockpit (infotainment)	0.5 kW
Power demand	**9-12 kW**



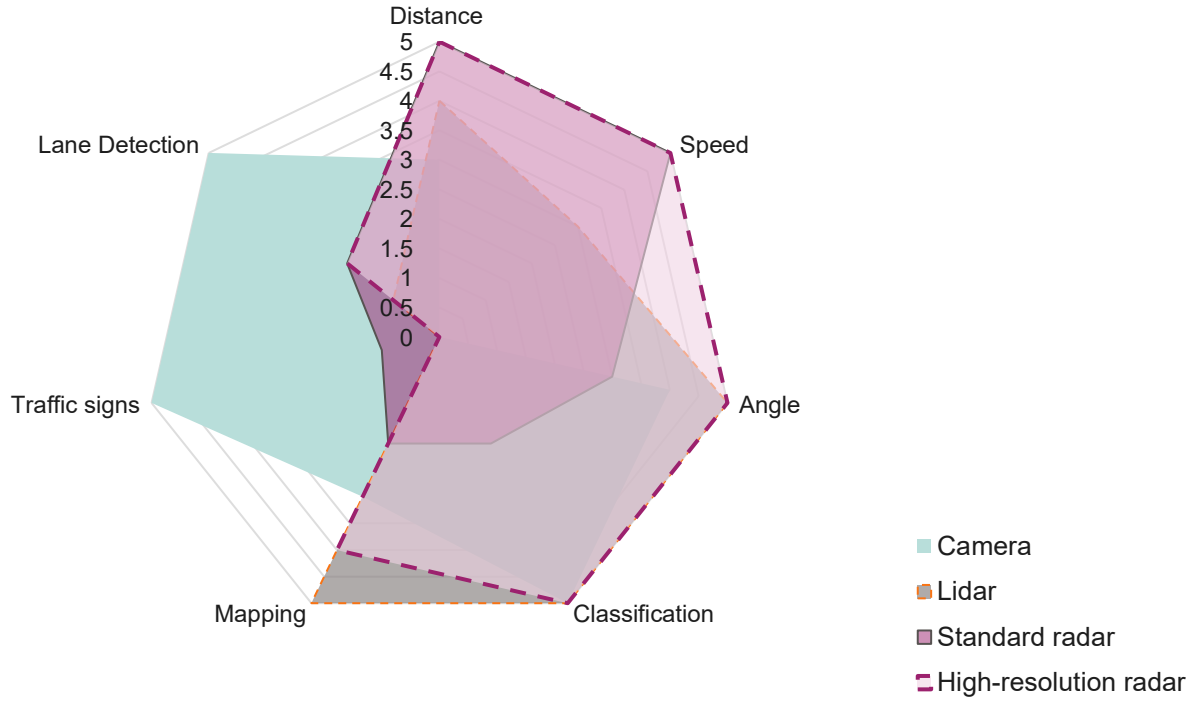
Growth of L1/L2/L2+ is the main driver of ADAS semiconductor content until 2030

Car production by degree of automation (SAE level)



Market research companies; Infineon

Radar is essential to meet decisive requirements of ADAS/AD



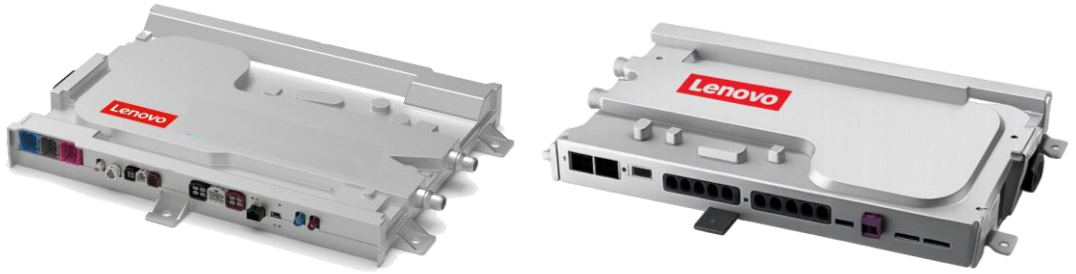
- Standard radar is the technology to detect distance and speed
- High-resolution radar significantly improves angle and classification

Infineon and Lenovo accelerate autonomous driving with high-performance SDV computing platforms

AURIX™ TC3x ASIL-D safety host selected for Lenovo's flagship AD domain controller units AD1 and AH1

Strategic design win in China

- AURIX™ TC3x was selected as ASIL-D safety host in Lenovo's flagship autonomous driving domain controller units AD1 and AH1



Safety and performance leadership

- Enables intelligent, energy-efficient and high-performance automotive computing platforms that power AI integration in SDVs
- Safety-certified control with integrated security, high-speed data exchange across in-vehicle networks
- Supports safety-critical real-time and low-latency applications in autonomous driving

AMD adopts Infineon's HYPERRAM™ for high-performance, low-power embedded applications

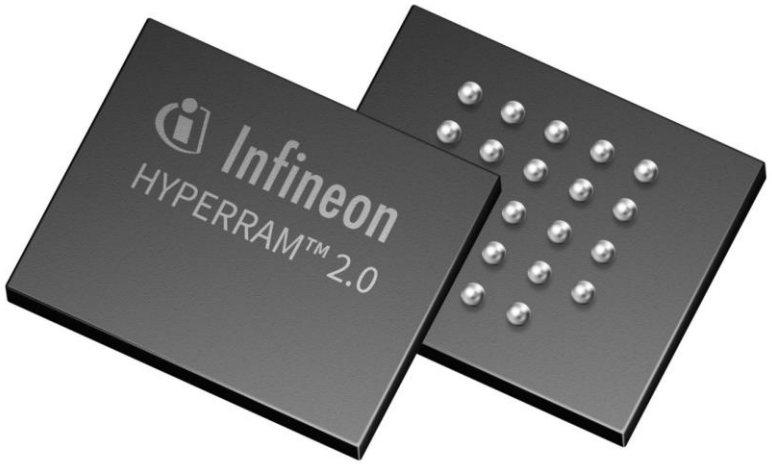
Validated high-bandwidth, low-power memory for AMD Spartan™ UltraScale+™ FPGA

Technical validation

- AMD validates Infineon's 64 Mb HYPERRAM™ pseudo-SRAM and HYPERRAM™ controller IP for Spartan UltraScale+™ FPGA
- Provides high-bandwidth, low-power memory for MicroBlaze™ V soft-core RISC-V processor

Advantages for system solutions

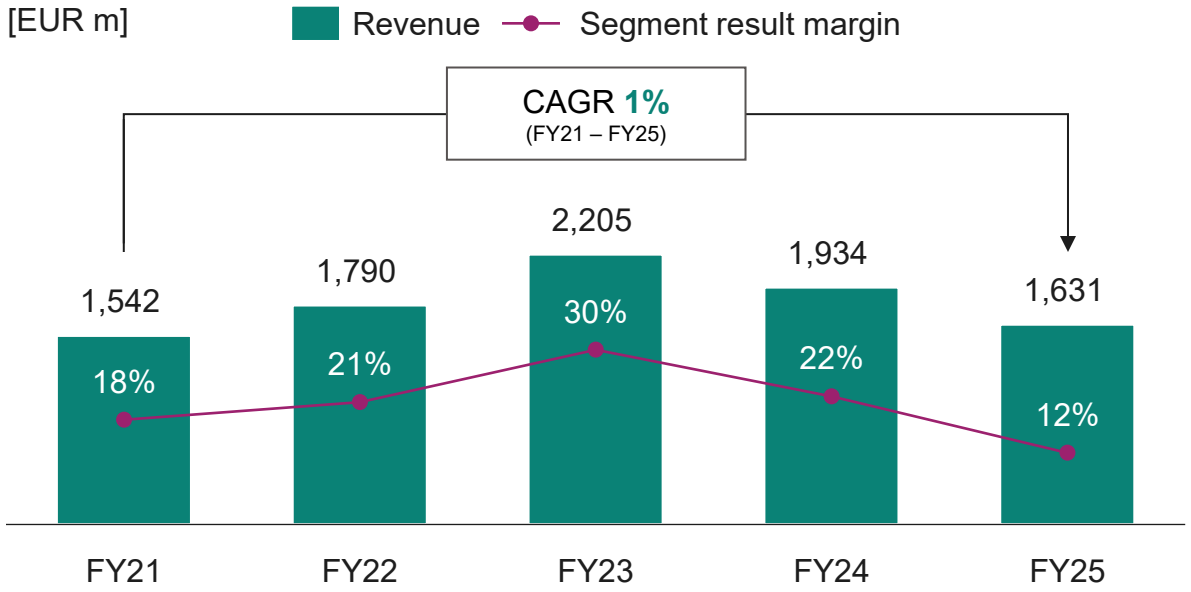
- Proven controller IP streamlines system integration and time-to-market
- Ideal for I/O expansion and printed circuit board-management capabilities
- Low pin count, low power consumption, cost-efficient designs
- Robust platform for embedded applications



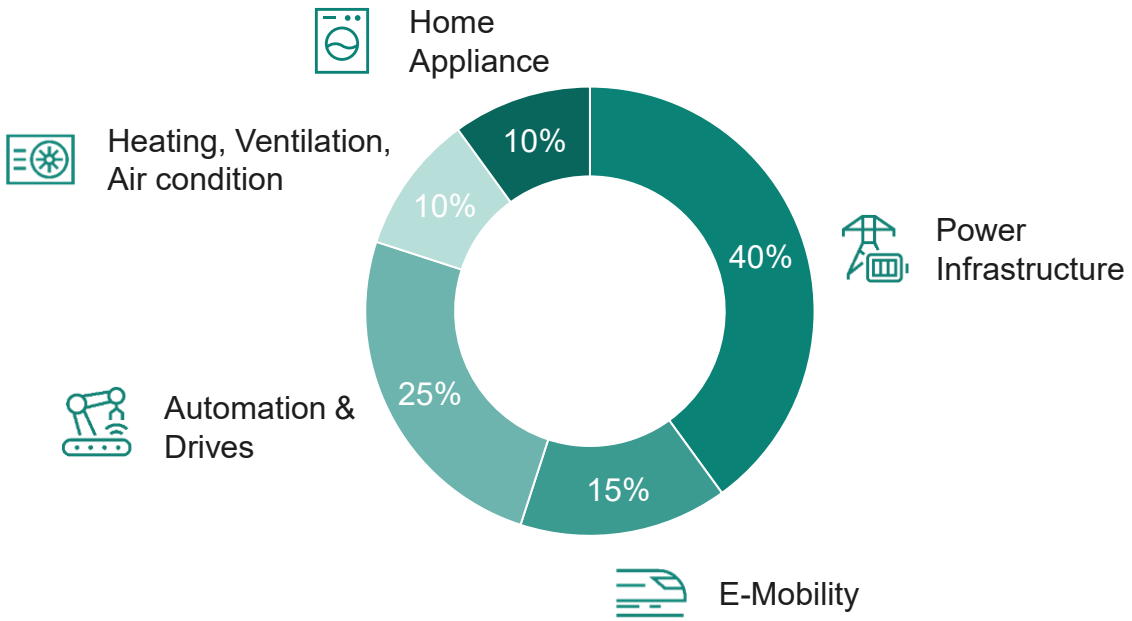
Green Industrial Power

GIP at a glance

GIP revenue and segment result margin



FY25 revenue split by application



Key customers

ABB, Aalpitronic, ALSTOM, Bloomenergy, 中国中车 CRRC, GOLDWIND, INOVANCE, LG, Midea, OMRON, Rockwell Automation, Schneider Electric, SEMIKRON DANFOSS, SIEMENS, SMA, SUNGROW, Vestas, YASKAWA

Huge potential along entire green energy chain until 2030 according to IEA Net Zero scenario

Generation

Photovoltaic	**+ 10,300 GW**
Wind power	**+3,300 GW**

Infrastructure

Grid network	**$600bn annual investments**
Grid storage	**+2100 GW**
EV charging	**+110m chargers (public and private)**
Electrolysis	**+560 GW**

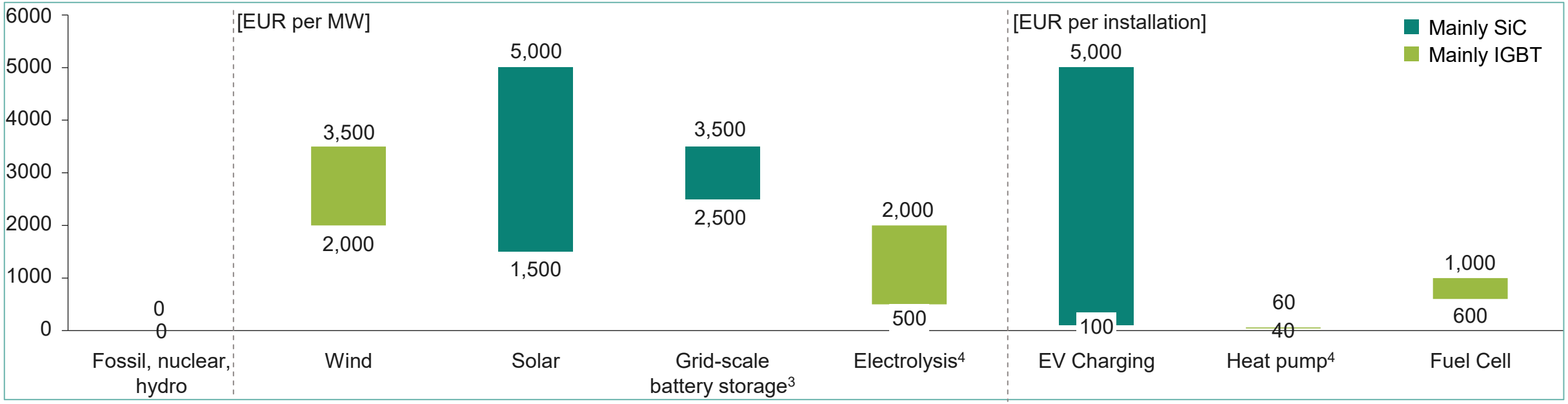
Consumption

Heat pump	**+420m units**
H_2 Fuel cell[1]	**+200k FC EV +200k FC Trucks**
eAviation | eMarine	

Note: Based on Net Zero Scenario (IEA) | Source: IEA - World Energy Outlook, November 2025,OMBDIA Power Semiconductors in EV Charging Infrastructure - 2025 [1] Internal Analysis

Green energy generation provides large business opportunities

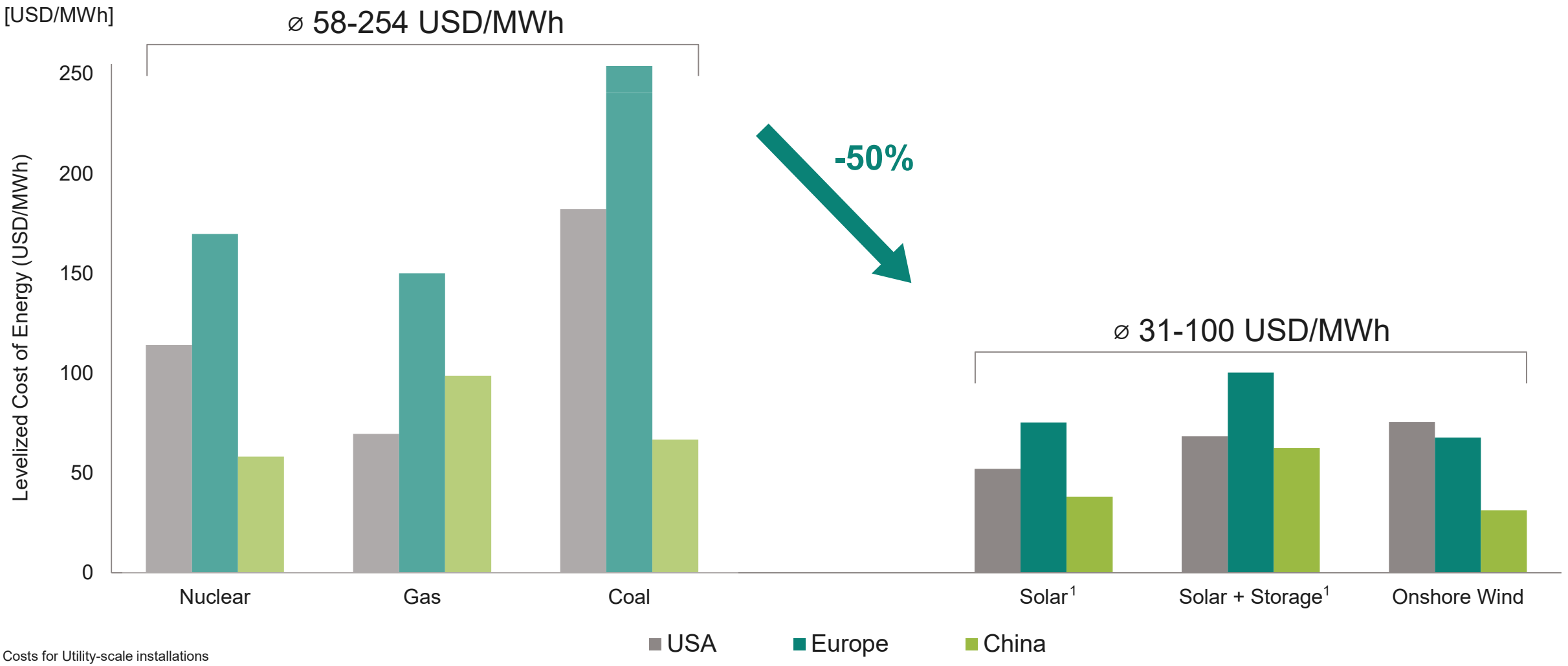
Power semiconductor content by application



Additions in 2024[1]	**115 GW**	**538 GW**	**62 GW**	**<1 GW**	**~6m inst.**	**22m inst.**	**5k inst.**
CAGR 2024-35	**13%**	**17%**	**30%**	**92%[2]**	**31%**	**16%**	**42%**

[1] IEA: World Energy Outlook, November 2025; Sector Tracking reports October 2023; internal Analysis
[2] Based on 270 GW pipeline (midpoint), >100% based on NZE requirements of 560GW
[3] Based on assumption 80% of total battery storage equals Grid-scale battery storage
[4] Additions in 2022, CAGR 2022-2030

Renewables are on average the cheapest source of energy



[1] Costs for Utility-scale installations
Based on Wood Mackinzie LCOE Levelized Cost Of Energy dataset, 2024

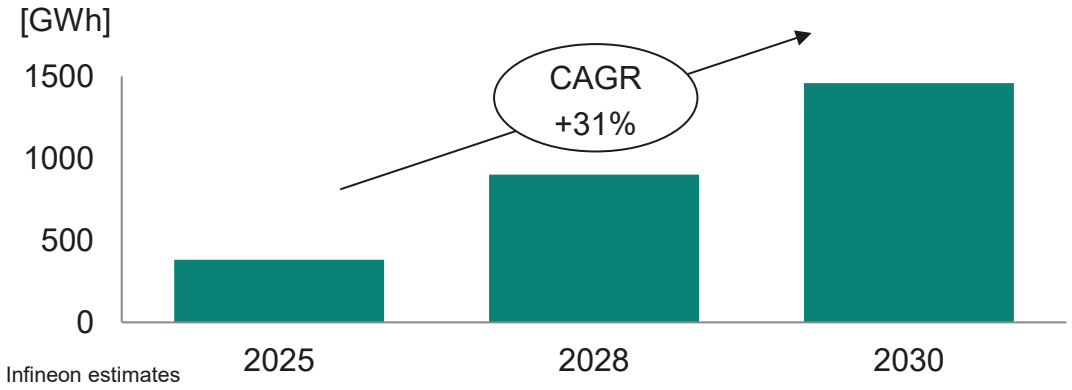
ESS: Commercial and Utility Storage Solutions with strong growth potential

Infineon's semiconductor content for energy storage solutions (ESS)

power	– IGBT discretes – SiC MOSFETs – Low & medium power modules – High-power modules
control & connectivity	– MCUs – Connectivity chips
analog & sensors	– Gate drivers – Current sensors

>€2,500 per MW

Global ESS battery shipment forecast



Close engagement with key players

- ESS inverter companies
- System integrators
- Battery OEMs

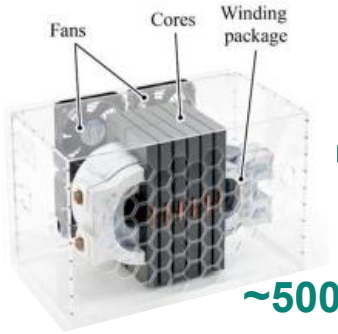
Solid-state transformers: new application for semiconductors with significant additional market potential

Conventional transformer

~20 t

Conventional transformer market
>USD 15bn

Solid-State transformer (SST)



~500 kg

~40x lighter[1]
~14x smaller[1]
~50% faster construction time

SiC

EasyPACK™

Infineon expects that **SST will replace a portion of the market**, specifically small power transformer with an expected market of **>USD 1bn in 2030**

Early involvement with leading electronics companies and hyperscalers on architecture & design in Europe, Americas and Asia, e.g:

DELTA solaredge

[1] Comparison refers to multi modular inverter (dual stage with HFT) based on own estimations.

Solid-state circuit breakers: increased safety, energy efficiency and reliability in power distribution

Analog circuit breaker

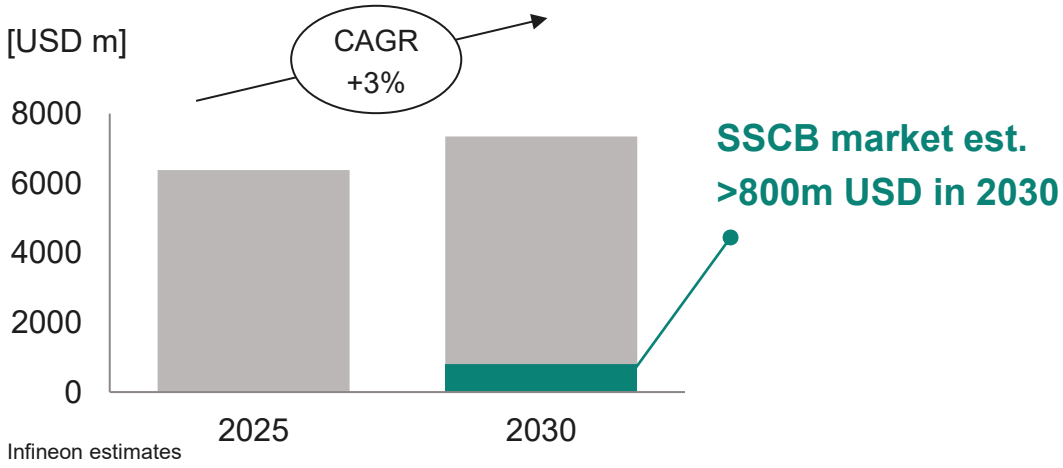
Traditional electromechanical analog circuit breakers protect electrical circuits against overloads and short circuits

Digital solid-state circuit breaker

Enables **smart energy management**:

- Ultra-fast overload and short circuit **interruption**
- Integrated **monitoring**
- **Remote control**

Industrial electromechanical circuit breakers



SSCB market est. >800m USD in 2030

ECPD, Electronic Circuit Protection Device

Courtesy of Siemens

SIEMENS

Adding CoolSiC™ JFET to MOSFETs: Infineon offers most comprehensive SSCB portfolio in the industry

Sampling now, start of production in 2026

Q-DPAK with CoolSiC™ JFET

More than 20 SSCB key customers and first Design-Wins with CoolSiC™ JFET

Energy savings

- ✓ Provides ground-breaking ultra-low $R_{DS(on)}$ 1.5m Ω at 750 V and 2.3 mΩ at 1200 V V_{BDss}

Robustness and reliability

- ✓ Designed and tested to handle extreme over-voltage, over-current and short-circuit conditions

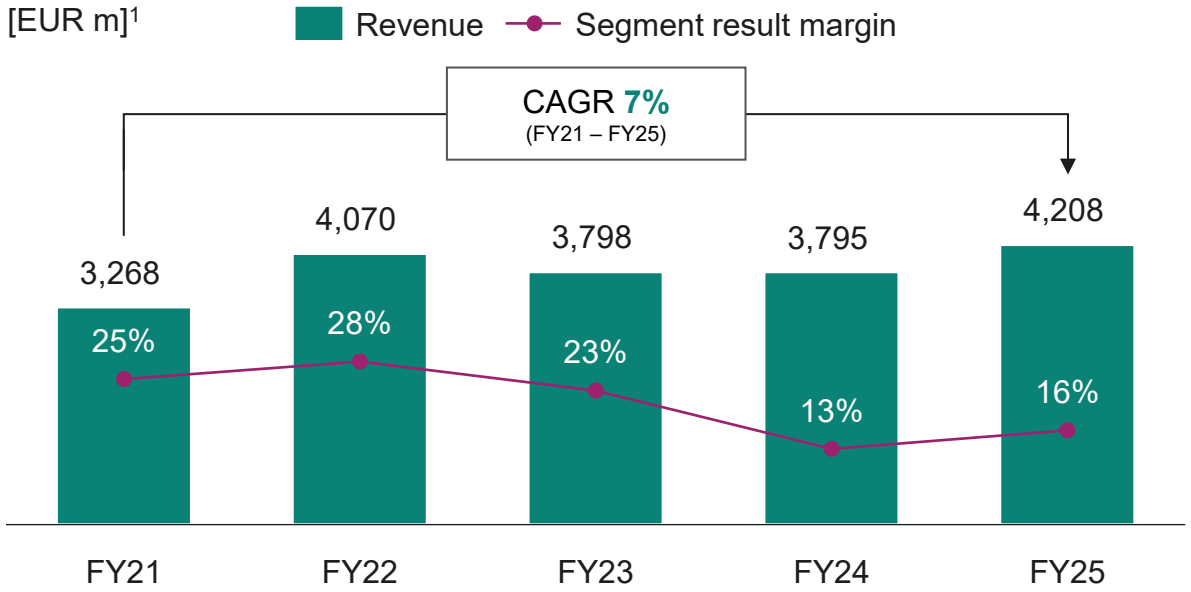
Integration and scalability

- ✓ Developed for ease-of-integration, scalability and manufacturability for industrial and automotive applications

Power &
Sensor Systems

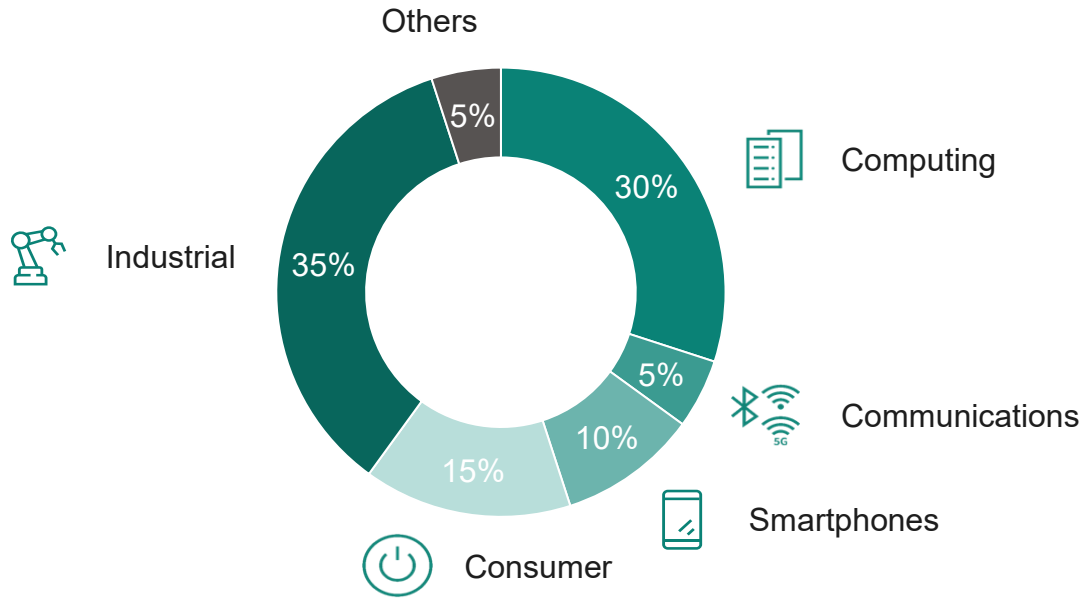
PSS at a glance

PSS revenue and segment result margin



[1] Transfer of "Sense & Control" business line from ATV to PSS from 1 January 2025 onwards not reflected in prior year numbers

FY25 revenue split by application



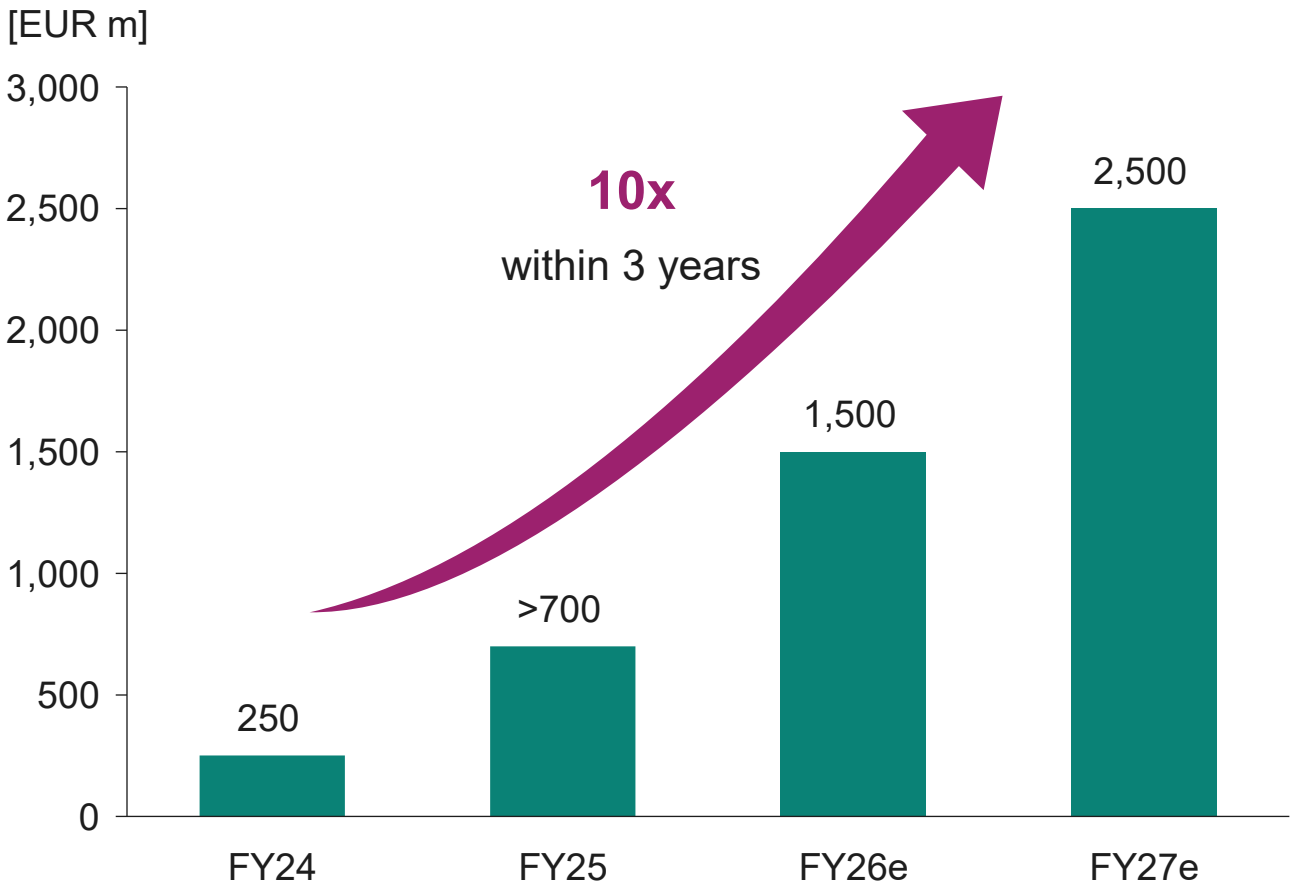
Key customers

amazon, cisco, DELL, DELTA, ERICSSON, ENPHASE, Goertek, Google, HUAWEI, hp, LITEON, Makita, Panasonic, SAMSUNG, solaredge, ZTE

Significant acceleration of our AI revenues due to most advanced technology and broadest portfolio

Infineon is growing together with customers driven by significant AI investments

Revenues from powering AI datacenters



In **FY25**, our AI server business achieved **>€700m** nearly **tripling** vs. FY24

We expect to **more than double** our revenue to **~ €1.5bn** in **FY26** and project to achieve **around €2.5bn** in our **2027 fiscal year**

Addressable market for us **in the range of €8bn to €12bn** by **end of decade**

Infineon's AI leadership enabled by system-first thinking and strategic differentiation by design

System understanding

Industry leading **system and innovation expertise along the entire power conversion chain**

Broadest product portfolio

Best-in-class performance and **mastering of all of the three relevant semiconductor technologies** (Si, SiC, GaN) including Power ICs

Customer-centric innovation

Accelerating innovation-to-customer value through high customer intimacy, system innovations, best-in-class efficiency and lowest cost of ownership

Quality and Manufacturing

High reliability and security of supply through rigorous quality standards and vertical integration based on leading in-house manufacturing capabilities

Infineon enables the architectural evolution from 125kW up to 1MW per rack

PSUs within server rack

Today ~125 kW/rack

IT payload

Power delivery & backup power

3-phase VDC power sidecar

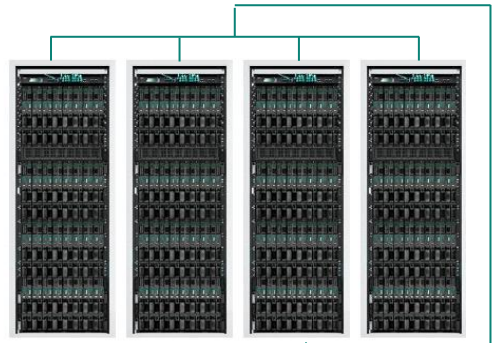
2027+ ~600 kW+/rack

IT payload

Power delivery & backup power

Hybrid microgrid

2029+ >1 MW/rack



IT payload

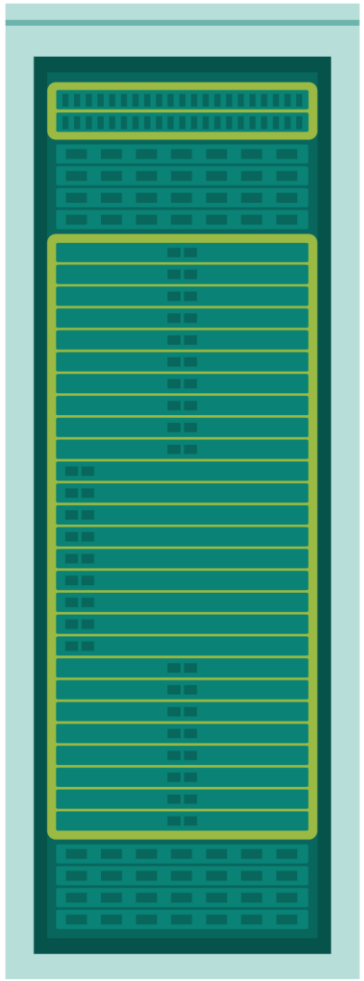
Power delivery & backup power through central infrastructure

~$15k

>$100k

Infineon Content

Leading performance high density AI Server for accelerated compute – Infineon BOM per AI server rack up to between $12k and $15k



Simplified visualization

Top of rack switches
x1 $200-215

PSU (Power Supply Unit)
x24 ~$120

Compute Tray
x10

Switch Tray
x9

Compute Tray
x8

~$120
Either or
~$70
x24

PSU (Power Supply Unit)

BBU (Battery Back-up Unit)

x36 → **GPU Board** (2 GPU + 1 CPU) ~$130 — 2nd stage

x18 → Power Delivery Board → **48 V Bus Converter** $70 - $150 — 1st stage

x108 → **Smart Network Interface Cards** ~$8

Protection (Hot-swaps, eFuses)
x >300 ~$3

Power System Reliability Modeling possible on every controller

3-phase VDC power sidecar – Infineon powers AI from grid to core for accelerated compute, driving further content growth

Server Rack

x72 (18x4)
Compute Blades

x32 (8x4)
Switch Tray

Power Sidecar

x30
PSU (Power Supply Unit)

x30
BBU (Battery Back-up Unit)

x10
PCS (Power Capacitor System)

x72
Mother Board

- **x1** — 2nd stage — **GPU Board**

- **x2** — 1st stage — **HV IBC**

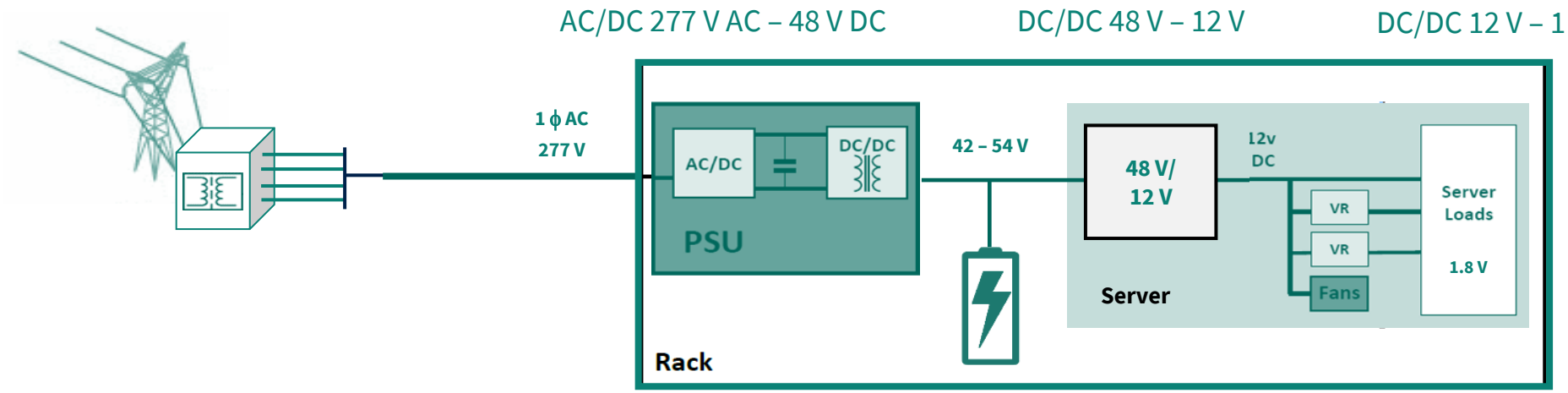
x288
Smart Network Interface Cards

Protection (hot swaps, eFuses)

Example of a potential 3-phase HVDC power sidecar architecture

With its energy efficient power semiconductors Infineon is serving all AI-related power conversion from grid-to-core

Power delivery network losses in an average AI data center



Average data center power flow efficiency today	97%	97.5%	90%	~85%
Efficiency potential from Infineon's leading power semi solutions[1]	98%	98%	94%	**~90%**

[1] Using GaN, SiC & vertical power modules

Innovative 3-phase PSU system solutions leverage system expertise and IP to deliver industry-leading performance and efficiency

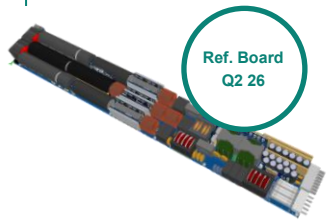
Infineon's solutions range from 3 kW to 30 kW

3.3 kW
1-phase PSU
η 97.4%
98 W/in^3
Si SiC GaN

8 kW
1-phase PSU
η ~97.5%
100 W/in^3
Si SiC GaN

12 kW
1-phase PSU
η ~97.5%
113 W/in^3
Si SiC GaN

16+ kW
3-phase PSU
η ~97.5%
100+ W/in^3
Si SiC GaN



27 kW
3-phase PSU
Si SiC

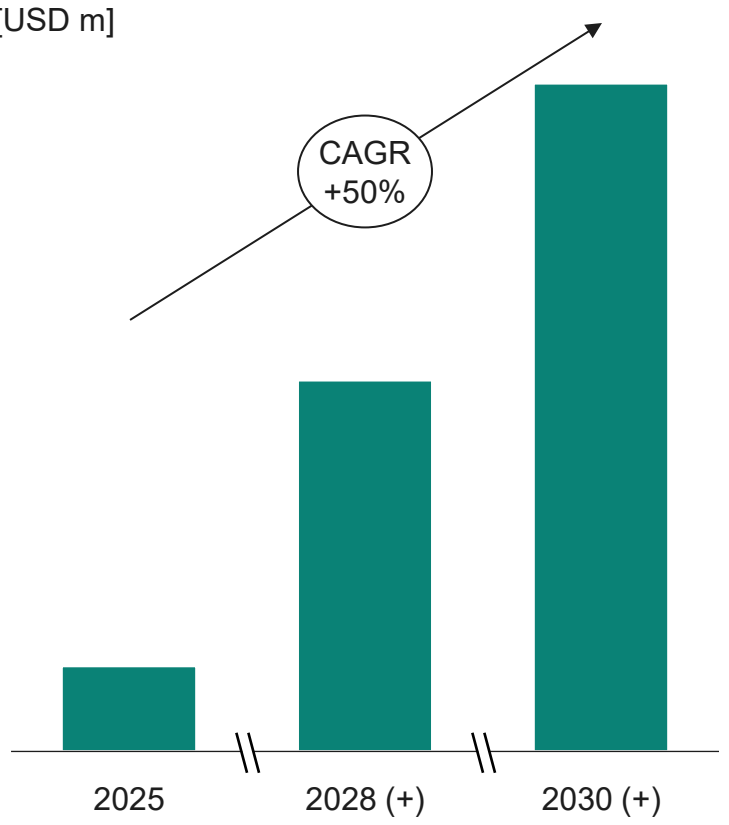
30 kW
3-phase PFC
SiC GaN

Rising power demands require the transition to advanced three-phase PSU architectures

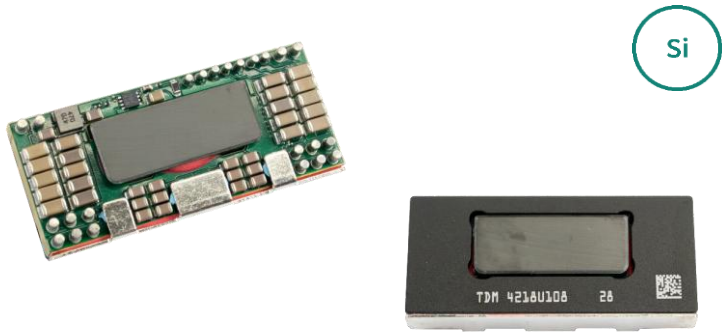
1-phase PSU → 3-phase PSU

Infineon offers a broad portfolio of HV & MV IBCs for current and future AI server rack architectures

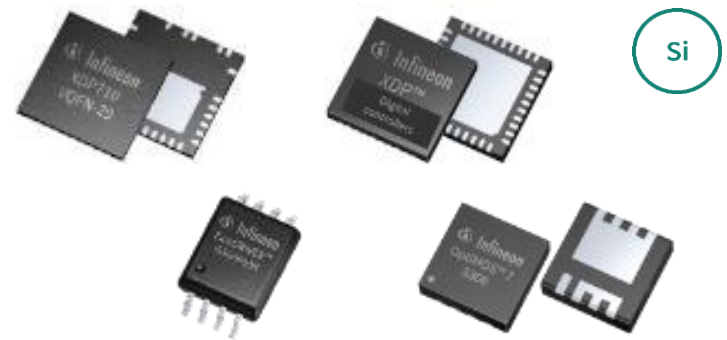
SAM IBC Market



Infineon IBC Module for AI



Discretes



Meeting customer requirements

1. With a wide range of **IBC topologies**, Infineon is serving a multitude of data rack configurations while ensuring cost-effectiveness
2. **Quality and Reliability** to improve mean time between failures in complex systems
3. **Power density** as GPU power increases
4. **Efficiency for** total cost of ownership
5. **Thermal Management** in air / liquid cooled environments
6. **Supply security** with 2nd source and fast time to market

Highest-density VRM modules enable true vertical power delivery adjacent to the processor

0.4 A/mm²
Molded package
2011

0.6 A/mm²
Chip embedded
2021

1.0 A/mm²
Gen 1 power module
2024

x2

1.5 A/mm²
Gen 2 power module
2024

2.0 A/mm²
Gen 3 power module
2025

x2

>3 A/mm²
Backside mounted
2027

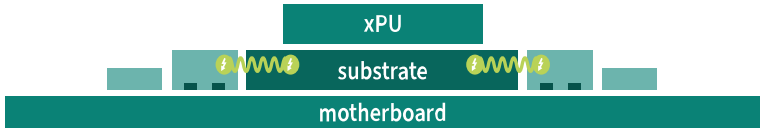
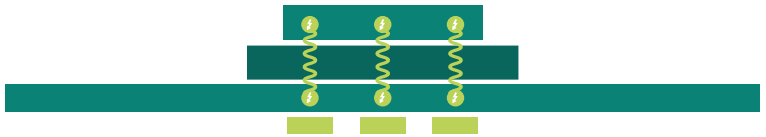
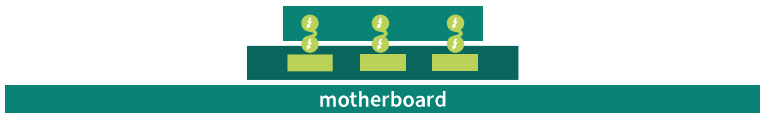
>4 A/mm²
Substrate embedded

today

tomorrow

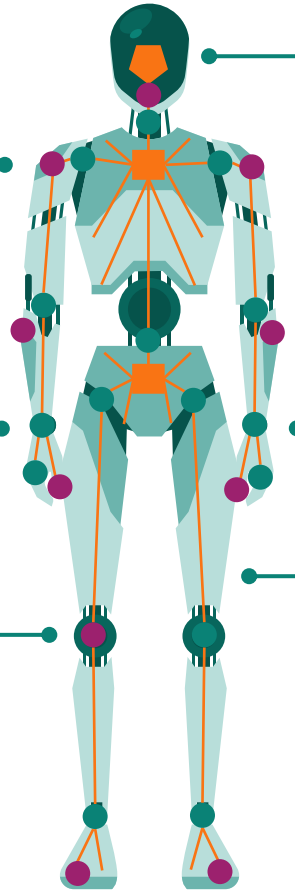
Future Solutions
>3.0A/mm²

Infineon's cutting edge vertical power delivery solutions significantly reduce power losses in AI data centers further

Lateral Power Delivery	**Discrete** (Lateral) + Power stages, inductors and capacitors located next to the processor + Lowest cost, with established eco-system and quality record + PDN losses exceed 100W for GPU currents beyond 850-1000A	Lumped PDN[1] 90-140µΩ	
Vertical Power Delivery	**BVM – Backside Vertical Module** (Vertical) + Increases power density by eliminating required spacing between multiple smaller modules + Simplifies motherboard design by eliminating routing of input power and control signals under processor	Lumped PDN[1] 10-15µΩ -89%	
Vertical Power Delivery	**SiVR – Substrate integrated Voltage Regulator** (Vertical) + Reduces substrate PDN losses by additional 10-15% + Removes substrate interconnect current limitations	Lumped PDN[1] 7-10µΩ -93%	

[1]total resistance of Power Delivery Network

We empower humanoids to sense, move, act and connect. Safe and secure.



Processing

MCUs, motor control ICs, security ICs

Connectivity

Wi-Fi, Bluetooth®, NFC, Ethernet, EZ-USB™

Power

Power switches incl. Si and GaN, DC-DC conversion, voltage regulators

Storage

NOR-Flash, SRAM

Analog

Gate drivers, analog amplifiers, data converters

Sensing

Magnetic, capacitance, current, vibration, pressure, SiMic, ToF, radar

control & connectivity analog & sensors power

Si SiC GaN

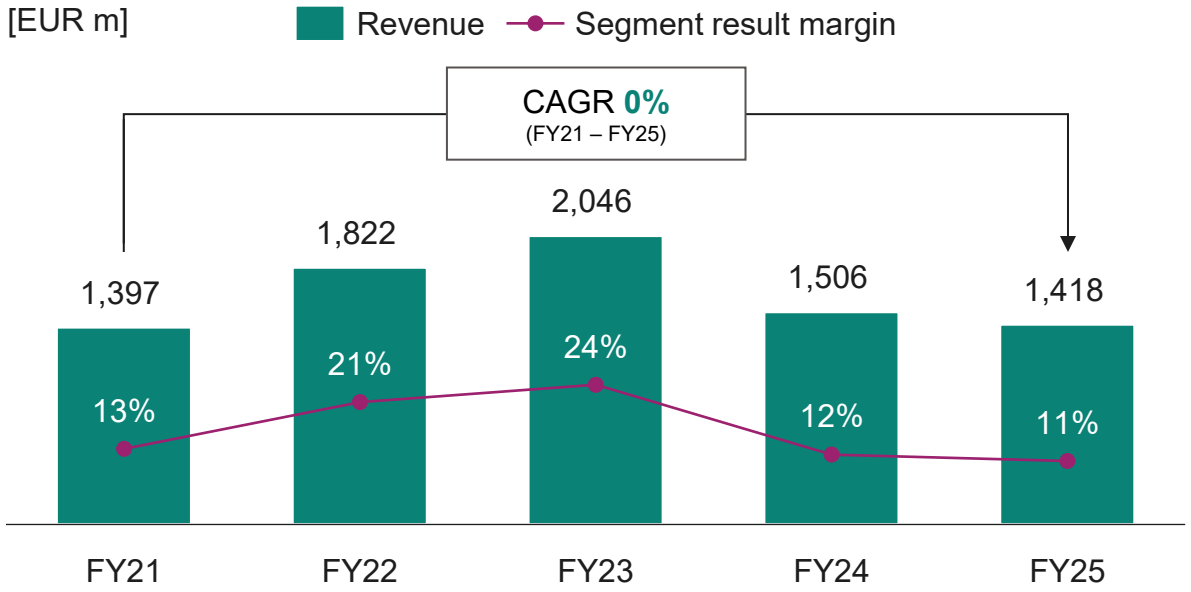
~$500

Infineon's addressable content per humanoid robot

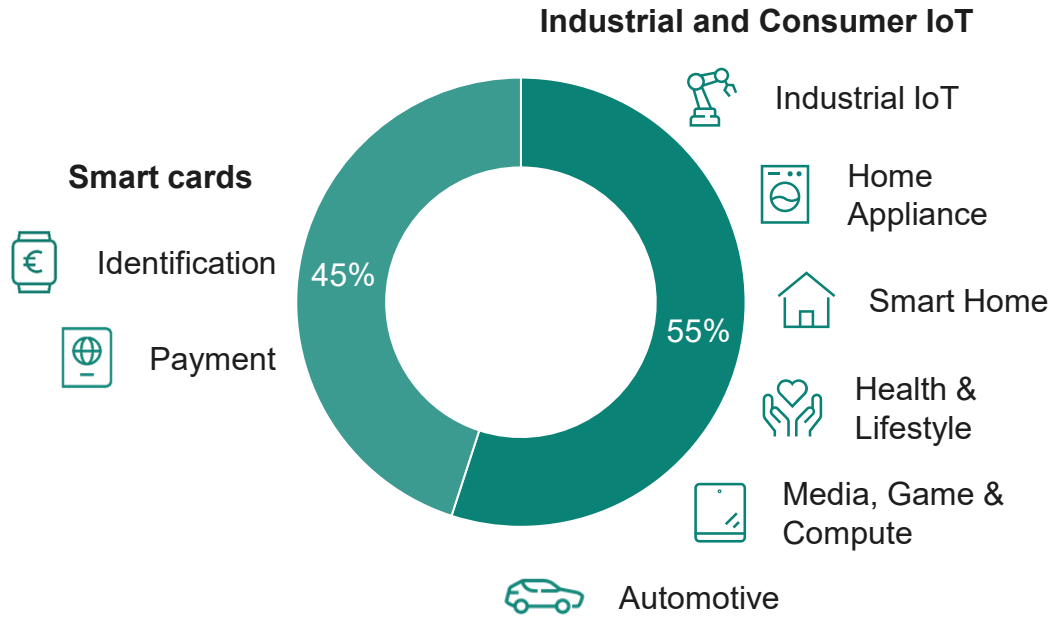
Connected Secure Systems

CSS at a glance

CSS revenue and segment result margin



FY25 revenue split by application



Key customers

AdvanIDe, amazon, arlo, AUSTRIACARD, cpi card group, GPO, Haier, Hisense, hp, IDEMIA, Midea, Nintendo, PERFECT Plastic, Raspberry Pi, SAMSUNG, SONY, THALES

Providing the essential building blocks compute, connectivity, security, and software

Consumer

Industrial

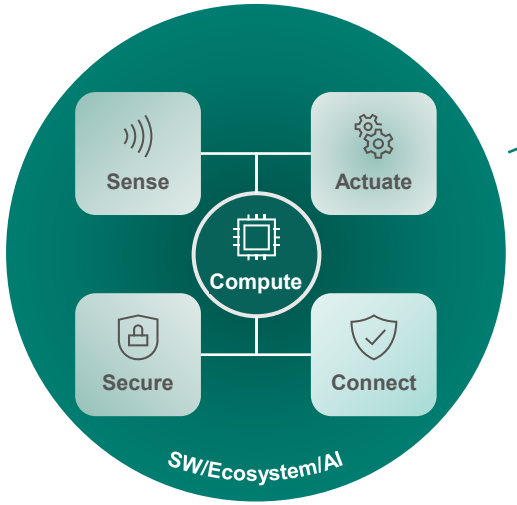
Automotive

Compute

PSOC™ and **XMC™ micro-controllers** allow customers to enable smart, connected products

Security

OPTIGA™, SECORA™ and TEGRION™ solutions provide robust embedded security for IoT devices, authentication, payments, identification, and access control



Software

DEEPCRAFT™ Studio and **ModusToolbox™ software** simplifies and accelerates development for Infineon MCUs

Connectivity

AIROC™ Wi-Fi and **Bluetooth®** products provide ultra-robust, low-power wireless communications

CSS seamlessly interconnects **compute, connectivity, security, and software** - the essential building blocks of digitalization

Infineon's MCUs at the heart of every IoT and Edge AI application

New compelling MCU platforms

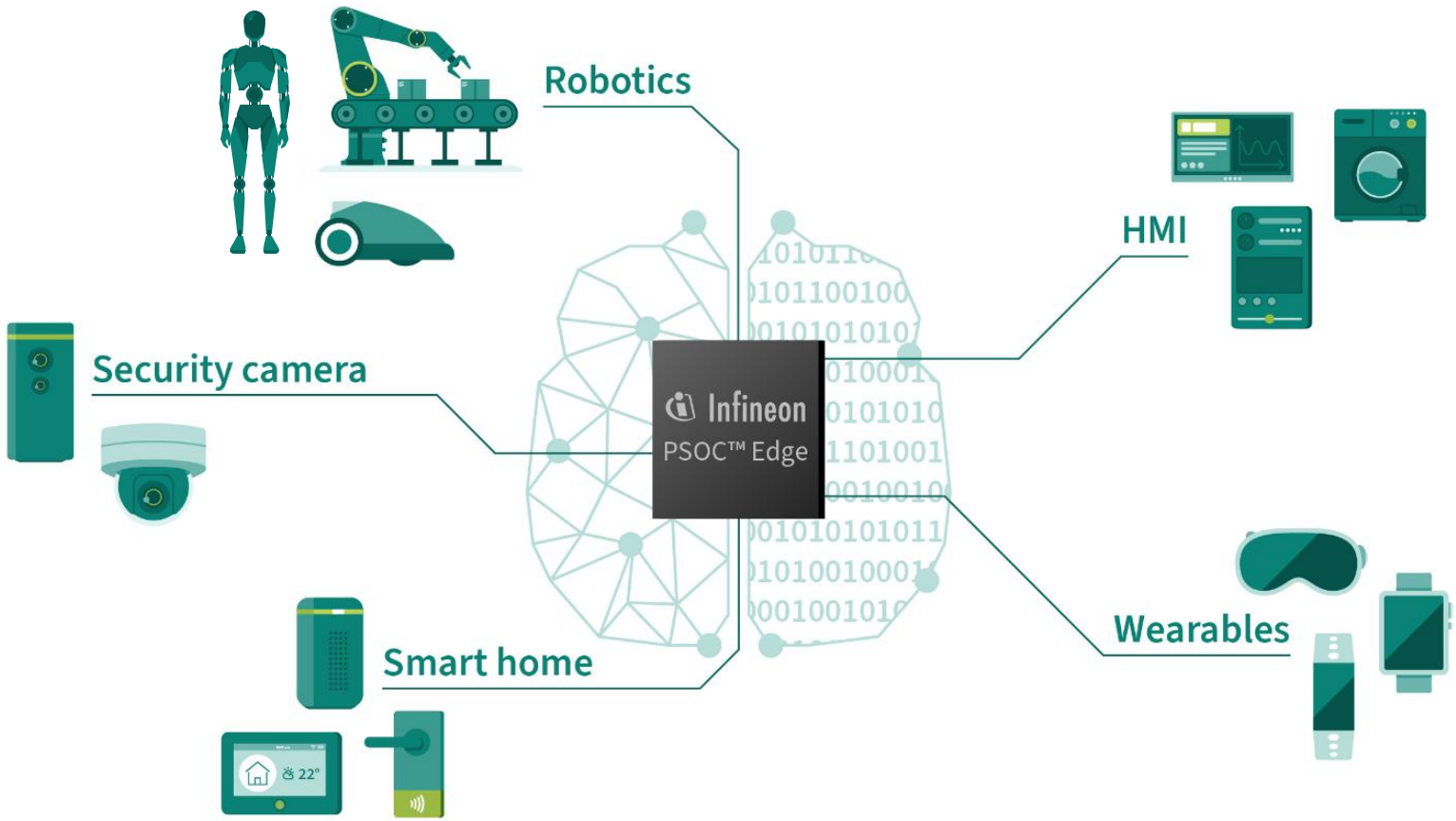
PSOC™ Edge

PSOC™ Control

PSOC™ Connect

- Broad application range in **Edge AI**, **IoT, Consumer**, and **Industrial**
- Strength in **low power**, **high performance**, **security**, and **reliability**
- Roadmap focus on **AI**, **security**, and **integrated connectivity**

PSOC™ Edge – Enables a new generation of responsive machine learning devices

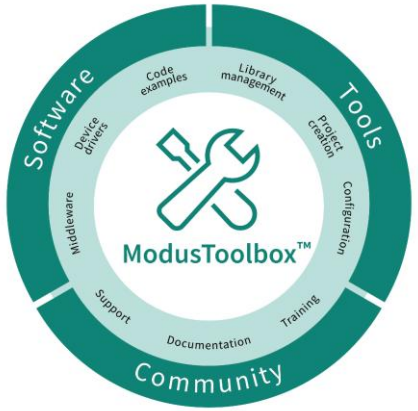


Software with maximal ease of use

DEEPCRAFT™ Studio

- Infineon's Edge AI development platform
- Data collection & pre-processing, model training, model conversion & deployment
- Provides AI-models for a wide variety of applications

ModusToolbox™



- Infineon's modern, extensible development system
- Collection of development tools, libraries, and embedded runtime assets

Full journey from Edge AI model development to embedded software with flexible entry

Build a model
Bring your own model — OR
Buy a ready Model

› **Optimize & validate your model** ›

Develop your embedded product with Infineon's MCUs

DEEPCRAFT™ Studio	DEEPCRAFT™ Studio + Modus Toolbox™	Modus Toolbox™

Enabling connectivity with Infineon's broad wireless portfolio for IoT, industrial, and automotive applications

Wireless connectivity portfolio & advancements in ultra-wideband

Wi-Fi AIROC™

- **Comprehensive Portfolio**: Wi-Fi 4,5,6/6E and connected MCUs
- **Ultra-low power** consumption
- **Integrated MCUs** for simplified IoT design
- Advanced Wi-Fi 6/6E with **future-ready Wi-Fi 7** capabilities

Bluetooth® AIROC™

- **Full-featured Bluetooth® portfolio** with SoCs and modules
- **Low-energy focus** for extended battery life
- **Long-range Bluetooth® Low Energy (LE)** for industrial and automotive applications

Wireless Connectivity

Wi-Fi- & Bluetooth® Combo AIROC™

- Combines Wi-Fi and Bluetooth® in one module for **dual-connectivity use cases**
- Pre-certified for **faster time to market**

UltraWideband

- Acquisition of UWB pioneer **3db**
- **Target applications:** Car access and fine ranging

Infineon provides a comprehensive end-to-end embedded AI solution - CSS provides most essential building blocks

Edge AI solution offering

- **In-house AI Software DEEPCRAFT™ Studio**
- **Development & AI Ecosystem Modus Toolbox™**
- **Microcontroller PSOC™ & XMC™**
- **Connectivity & security solutions AIROC™ & OPTIGA™**
- **Sensors XENSIV™**

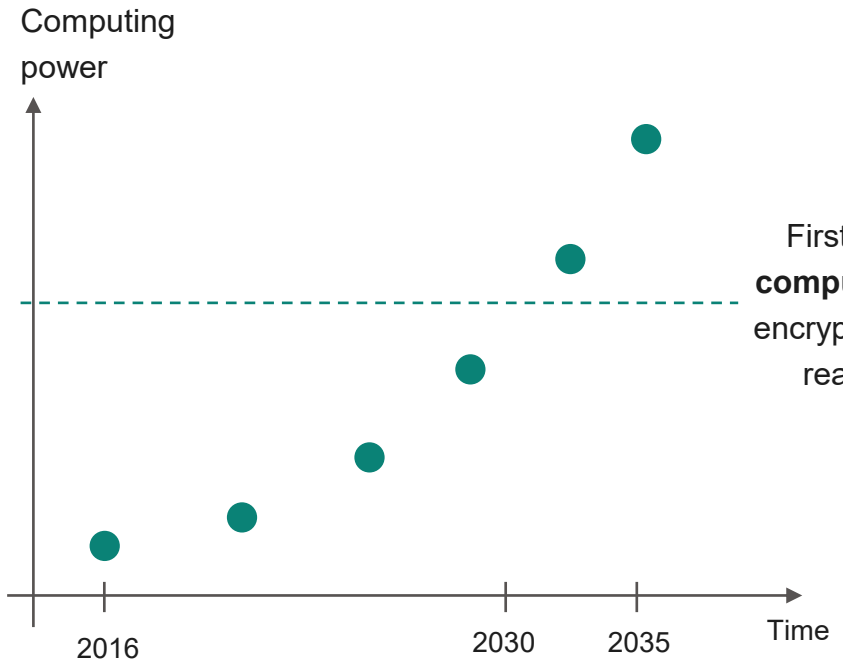
Customers‘ benefits

- Software perfectly tailored to Infineon hardware ensures **peak performance** and **simplified development**
- Comprehensive solutions **speed up time-to-market**
- Embedded AI solutions enable **edge processing**, **improving latency, and enhancing data privacy**
- Embedded AI solutions ensure smooth integration into **a wide range of applications**

Customer application

As quantum computing rises and introduces high security risks, Infineon serves as a trusted advisor in the PQC landscape.

Computing power of quantum computers



First universal **quantum computers** breaking today's encryption methods could be ready by **2030 – 2035**

Cybersecurity

- **Asymmetric** encryption algorithms (e.g. RSA, ECC) loose appropriate security
- **Symmetric** encryption algorithms are less effected

Threats

- To **sensitive data** from governments and public institutions
- To **products** with long R&D cycles

Legislations

- Government bodies are **working on legislations** to prepare for quantum-safe future

Infineon's post-quantum cryptography approach

Infineon is the **first company to receive the Common Criteria EAL6** for the implementation of **a PQC algorithm** in a security controller

Infineon **TEGRION™** product family of **next-gen security controllers** for long-lasting security and superior fault protection

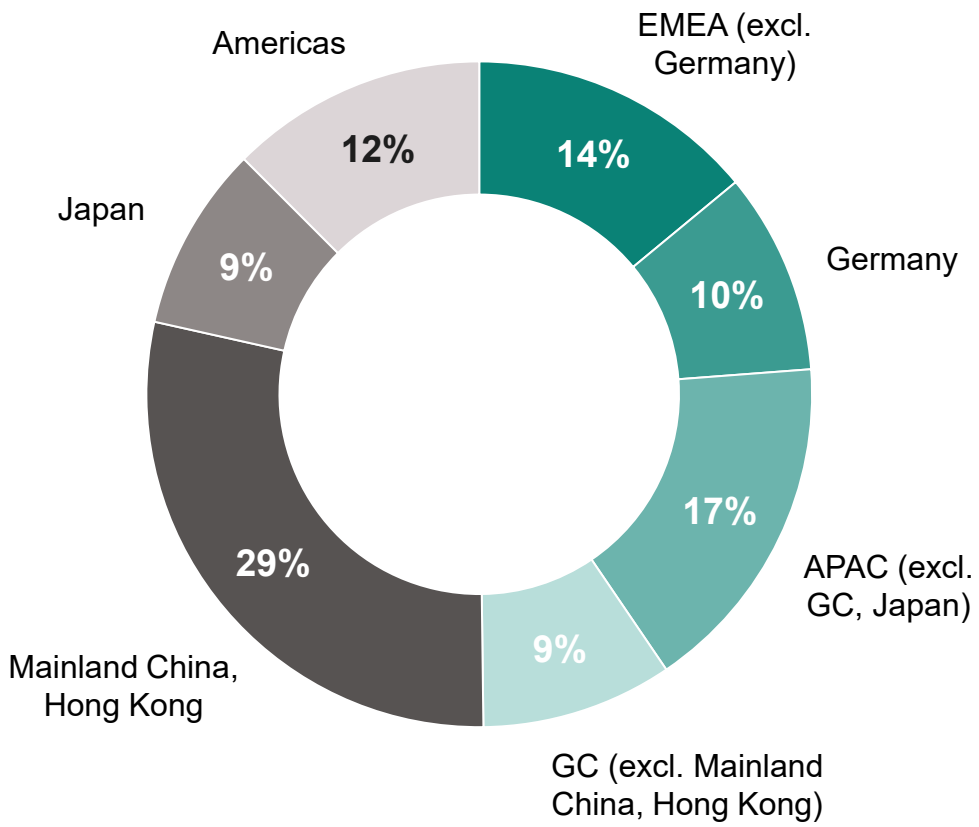
Partnering with customers, partners, and **the academic community** to prepare for a post-quantum future

Global team of experts and researchers dedicated to the PQC field

Selected financial figures

Strong presence in all regions; well-balanced customer portfolio; no customer represents more than 10% of total sales

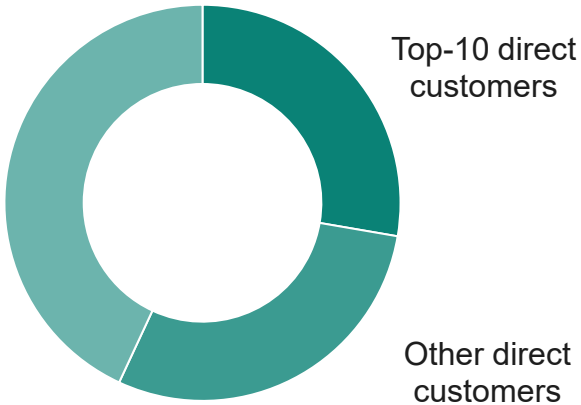
FY25 revenue by region



Revenue by sales channel

Distribution partners[1]

Top-10 direct customers[1]

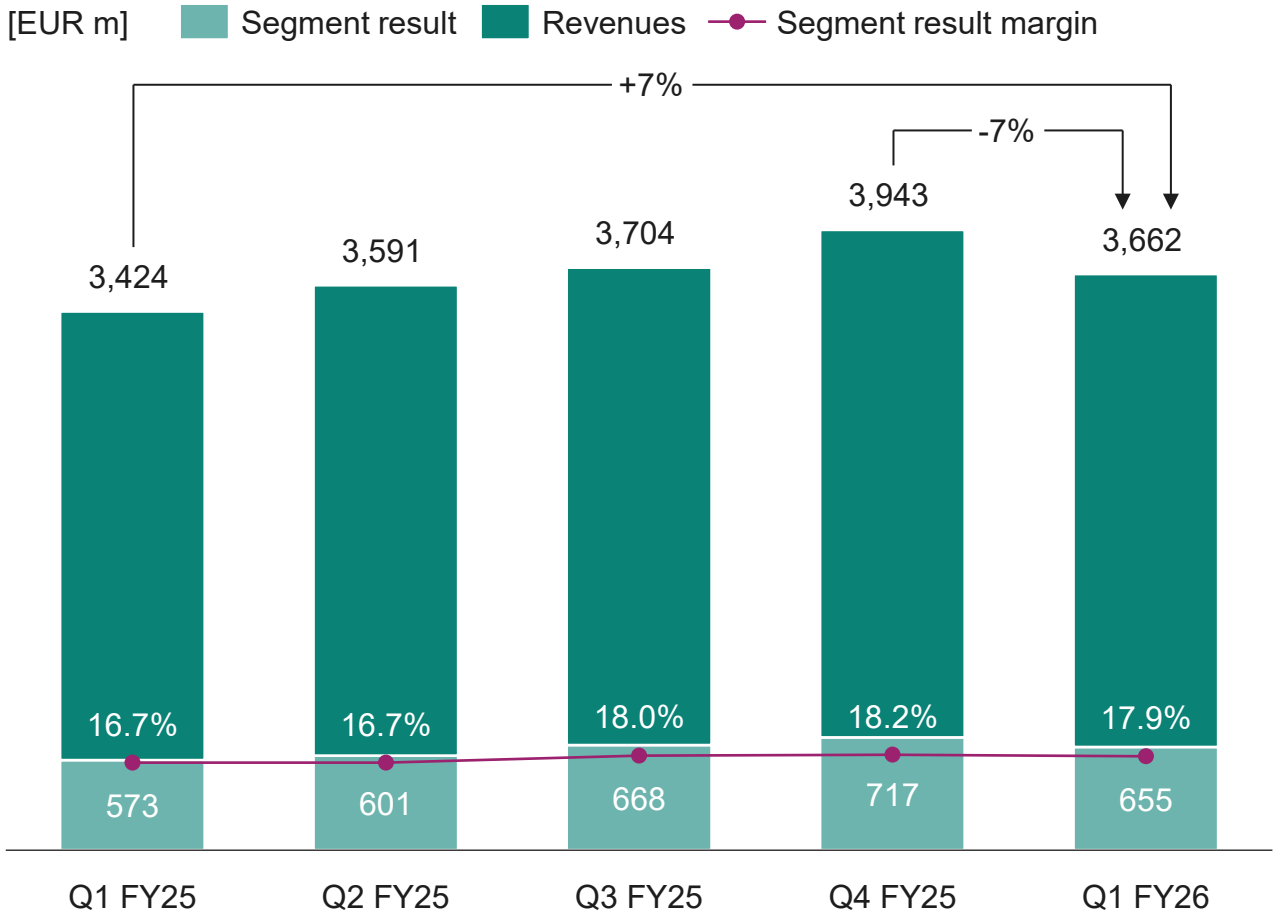


EMS partners[1]

[1] In alphabetical order

Group financial performance

Revenues and Segment Result

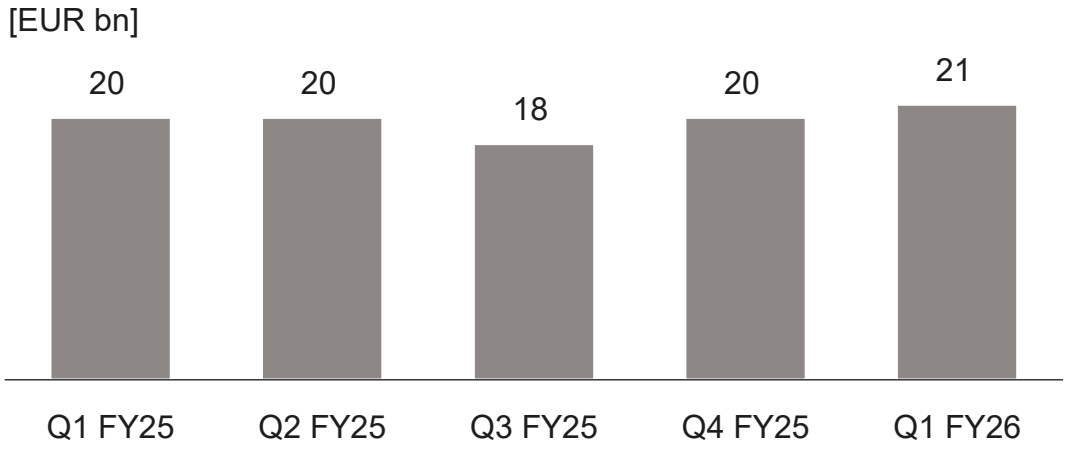


USD exchange rate

Average revenue exchange rate

	Q1 FY25	Q4 FY25	Q1 FY26
ø USD/EUR	1.07	1.17	1.16

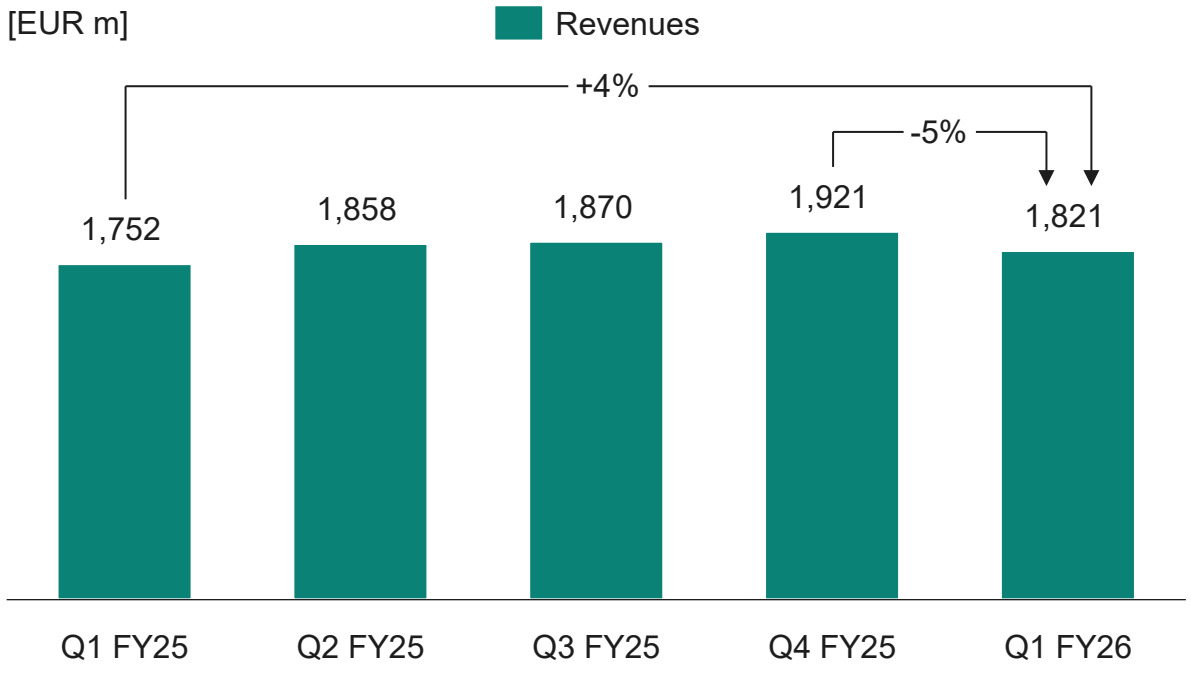
Order backlog[1]



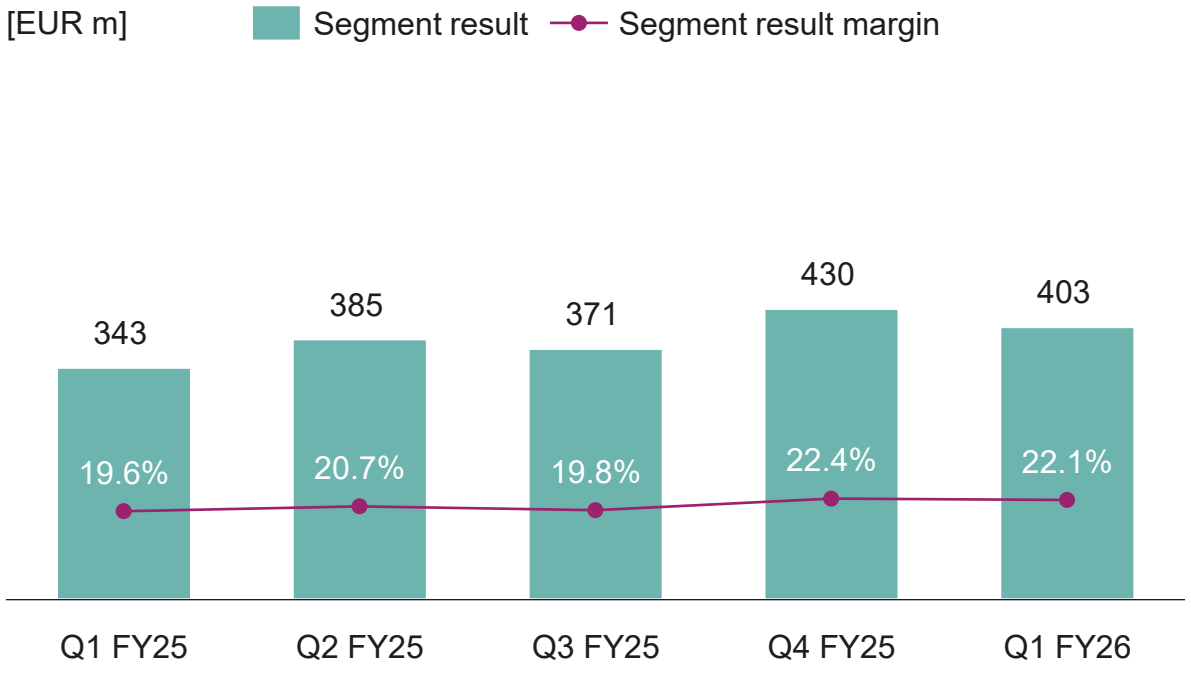
[1] See notes for definition

Automotive (ATV)

Revenues



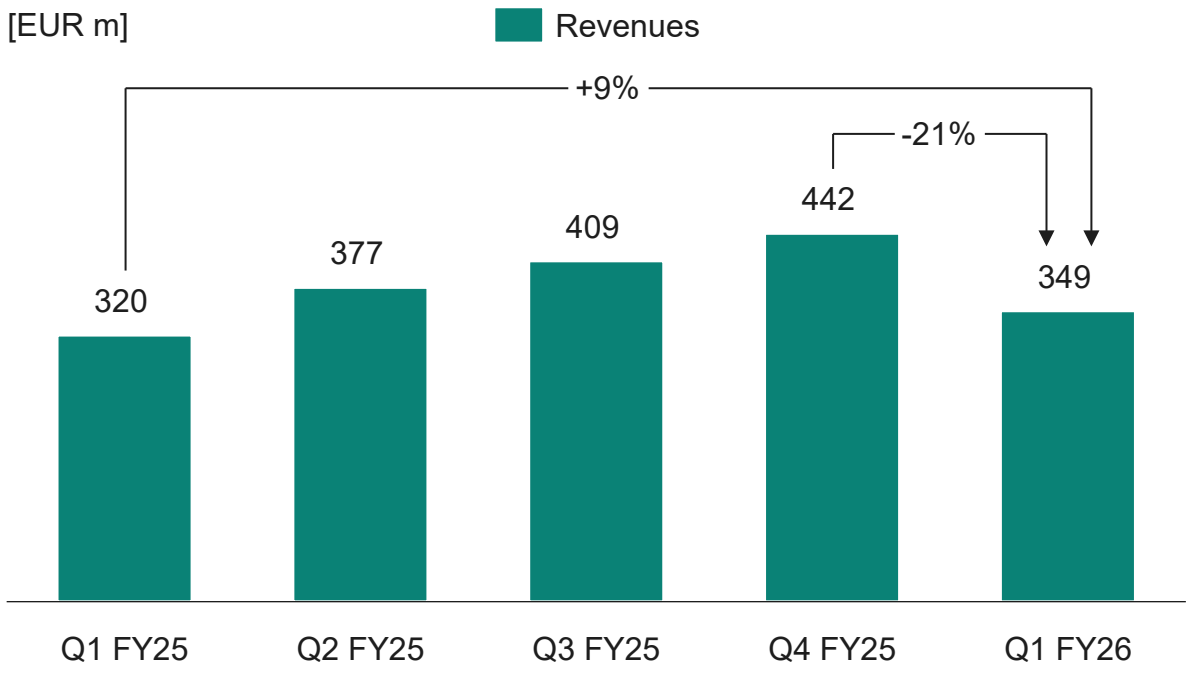
Segment Result



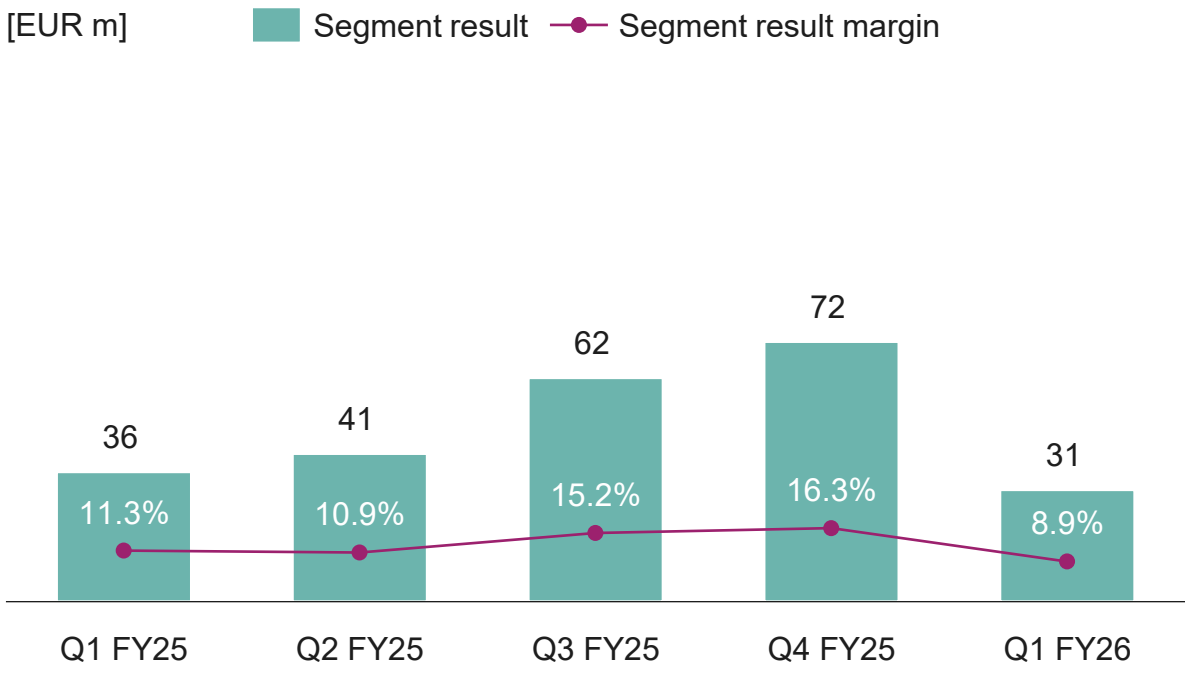
- Sequential revenue decrease due to seasonality and anticipated year-end customer inventory management.
- Segment result margin stable as volume declines were mitigated by lower underutilization costs and positive mix effects.
- Car volumes in-line or above expectations, while uncertainties related to China momentum and US tariff impacts persist.
- Software-defined vehicles, higher-level ADAS, comfort features and 48 Volt are key growth drivers, e-mobility is seeing slower momentum.

Green Industrial Power (GIP)

Revenues[1]



Segment Result[1]

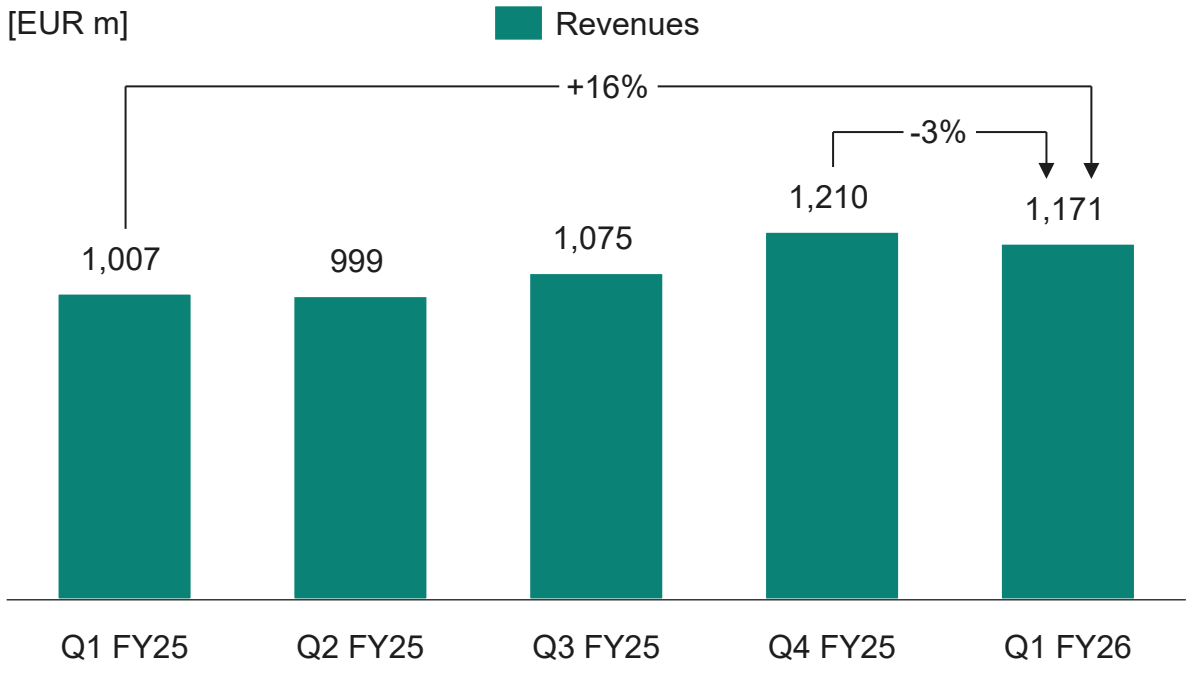


- Sequential revenue declines across all applications except grid-infrastructure.
- Segment result impacted by lower volumes.
- Strong grid-infrastructure investments - driven by AI data centers and a higher share of renewables - support mid-term growth.

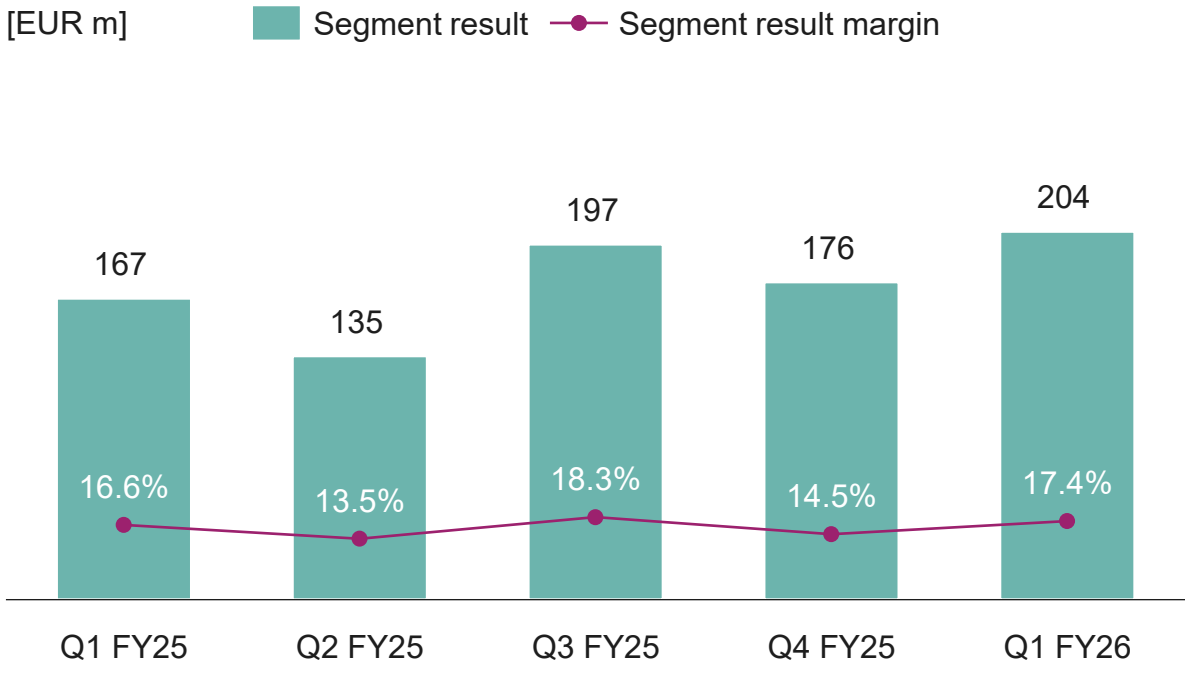
[1] Figures have been historically restated to reflect "Power Drivers & Signal ICs" product line transfer of from GIP to PSS

Power & Sensor Systems (PSS)

Revenues[1]



Segment Result[1]

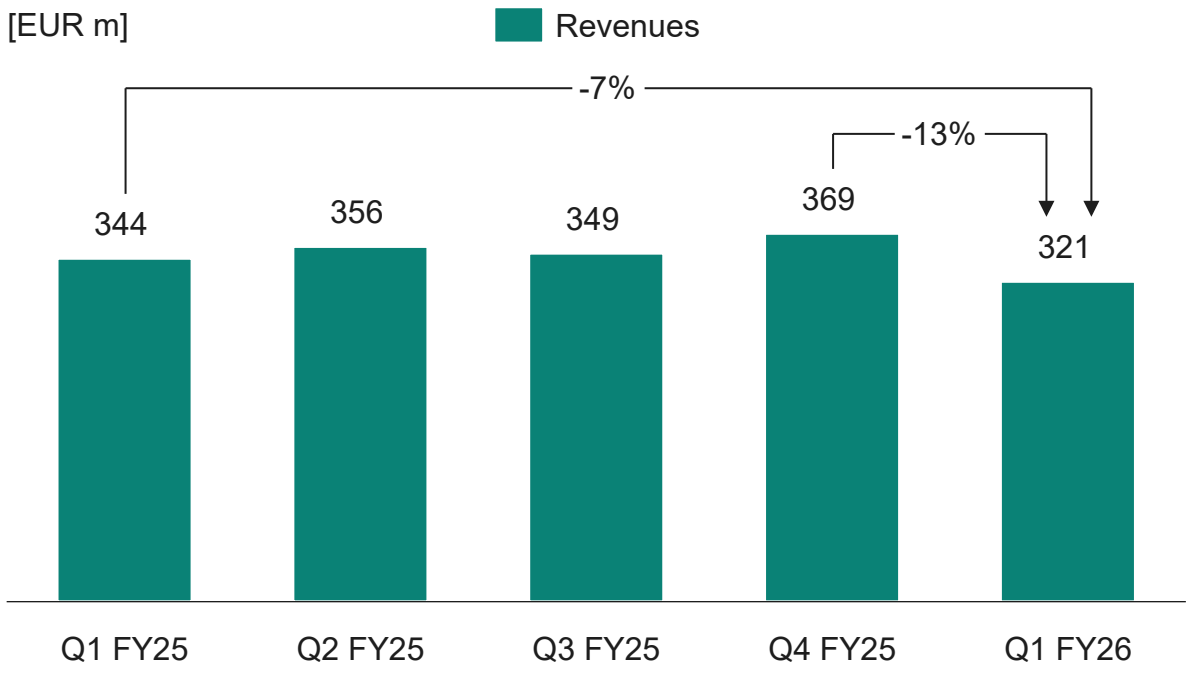


- Strong AI-server demand offset by smartphone seasonality and the phase-out of temporary fab fillers.
- Segment result improvement due to product mix and less idle costs.
- Consumer, general compute, and communications markets show first signs of a broader market pick-up.
- We confirm our FY26 AI revenue target of around €1.5bn and project AI revenues of around €2.5bn in FY27.

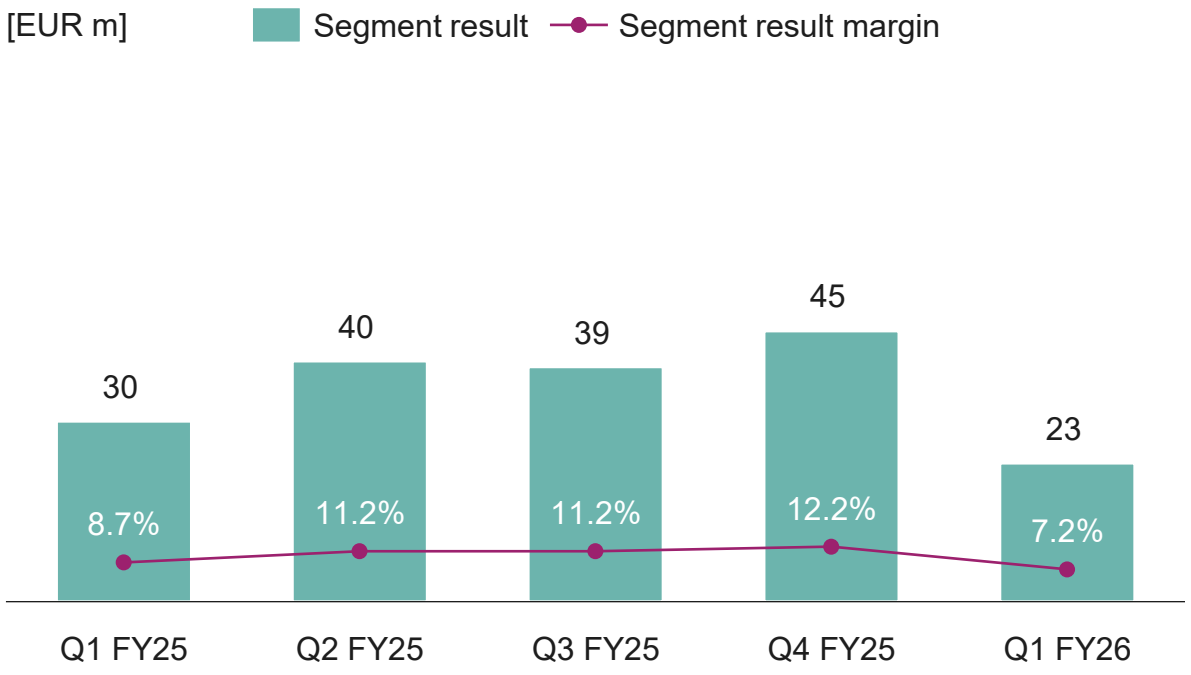
[1] Figures have been historically restated to reflect "Power Drivers & Signal ICs" product line transfer of from GIP to PSS

Connected Secure Systems (CSS)

Revenues



Segment Result

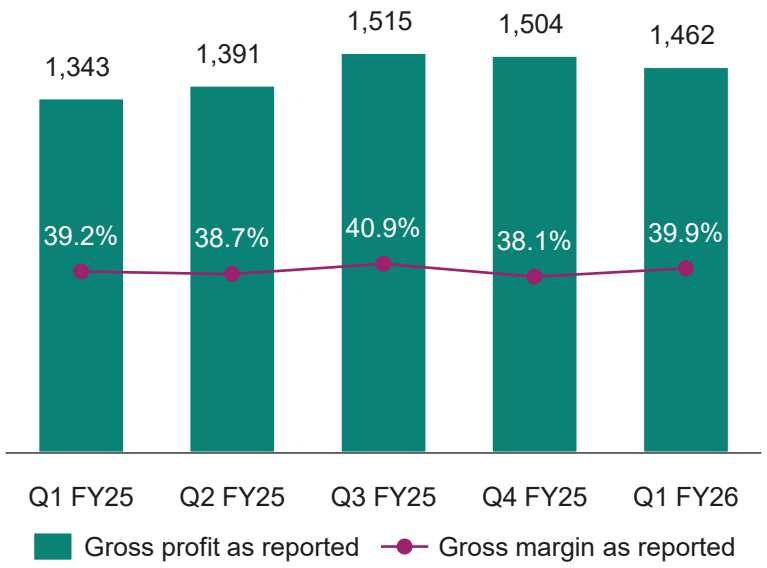


- Revenue decrease driven by a mix of seasonality and the fulfillment of CRA orders in the preceding quarter.
- Segment result margin decrease as a result of lower volumes.
- IoT markets remain subdued due to macro economic uncertainties.
- Edge-AI adoption will gradually unlock new industrial and consumer opportunities.

Gross margin and Opex

Gross profit

[EUR m]



Therein Non-Segment Result charges
[EUR m]

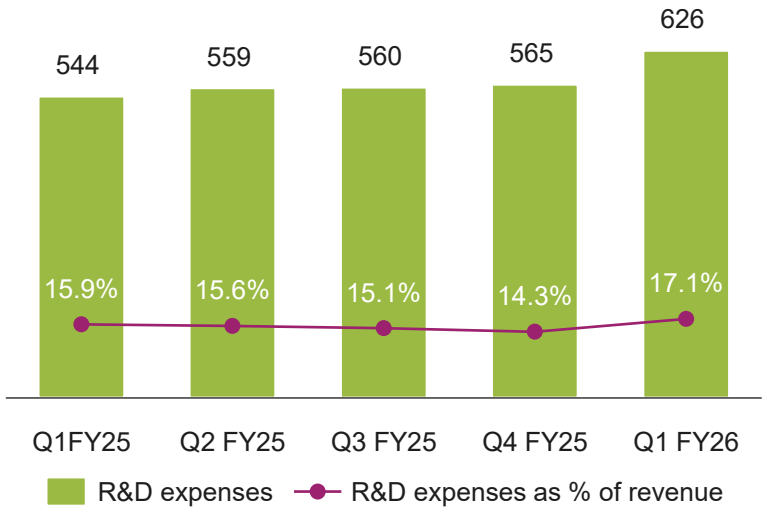
64	76	76	99	113

Adjusted gross margin [1]

41.1%	40.9%	43.0%	40.7%	43.0%

R&D

[EUR m]

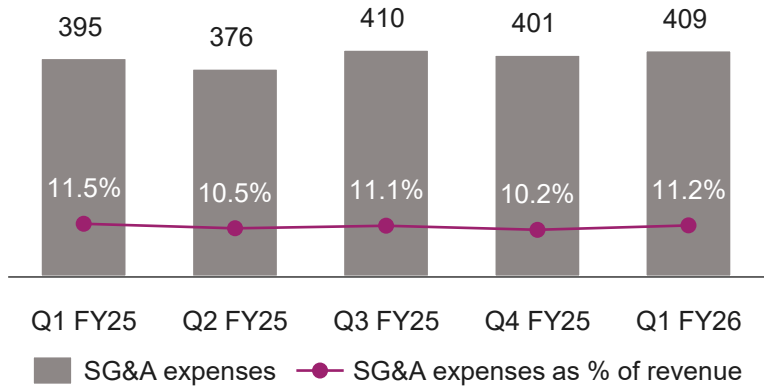


Therein Non-Segment Result charges
[EUR m]

18	14	18	17	35

SG&A

[EUR m]



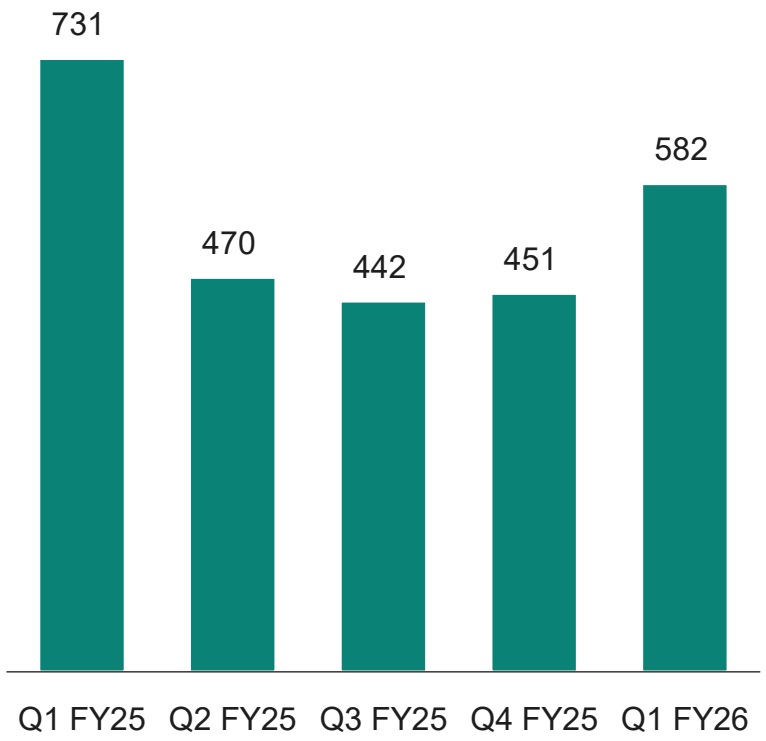
Therein Non-Segment Result charges
[EUR m]

56	53	50	67	77

Investments, Depreciation & Amortization and Free Cash Flow

Investments

[EUR m]

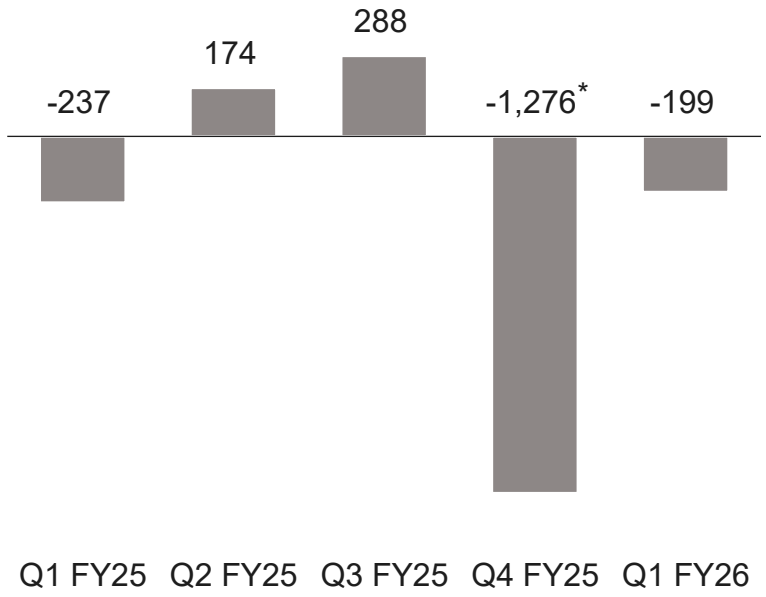


Depreciation & Amortization

[EUR m]

Free Cash Flow

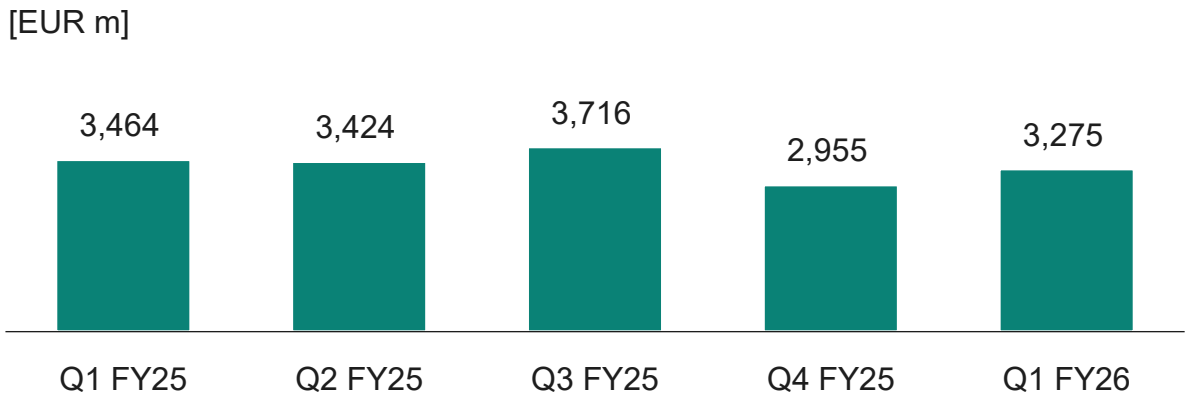
[EUR m]



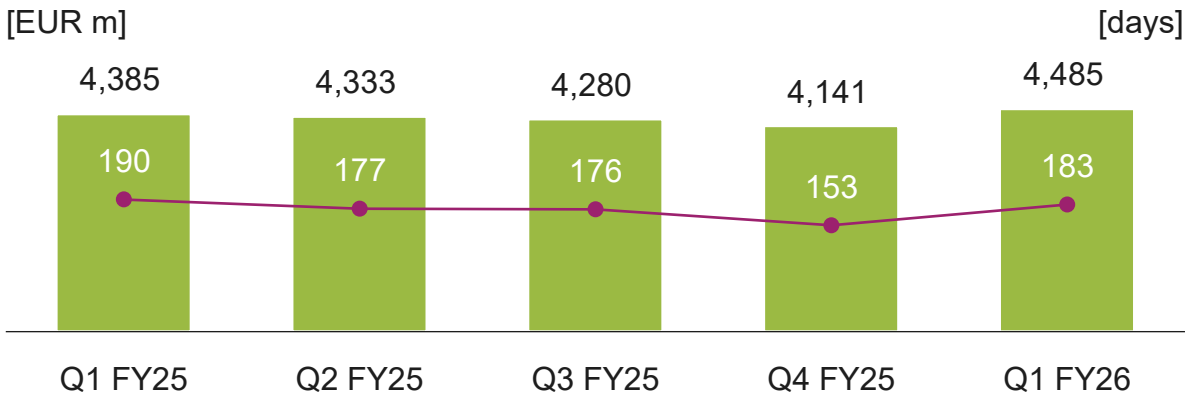
*FCF incl. 2,180m acquisition related outflows for Marvell's automotive Ethernet business

Working capital, in particular trade working capital components

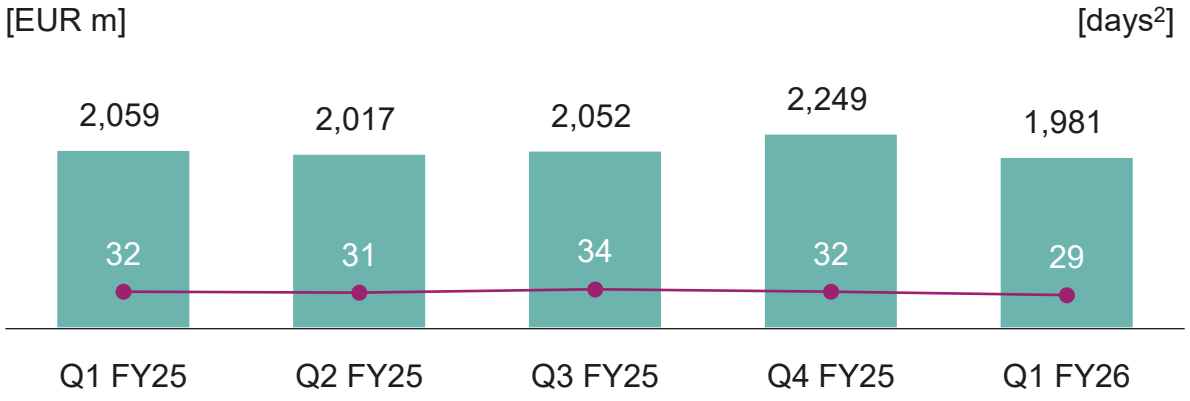
Working capital[1]



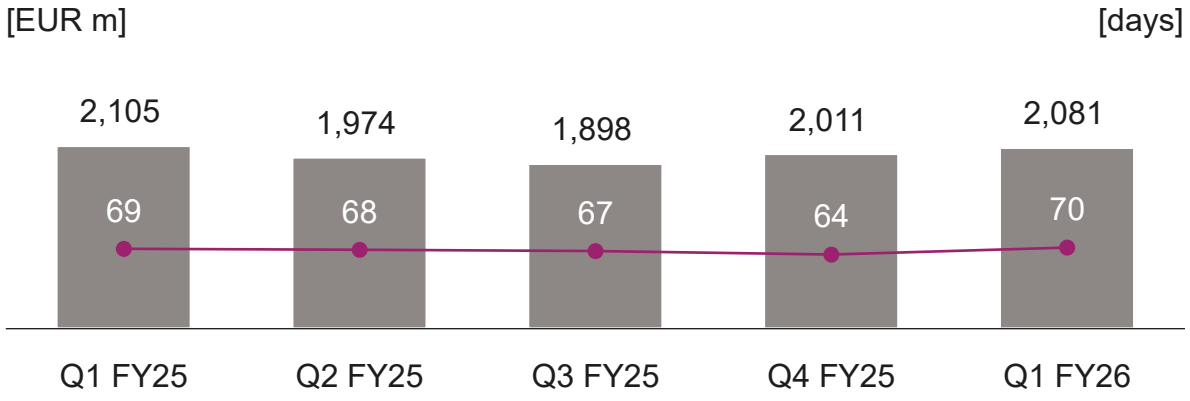
Inventories



Trade receivables



Trade payables

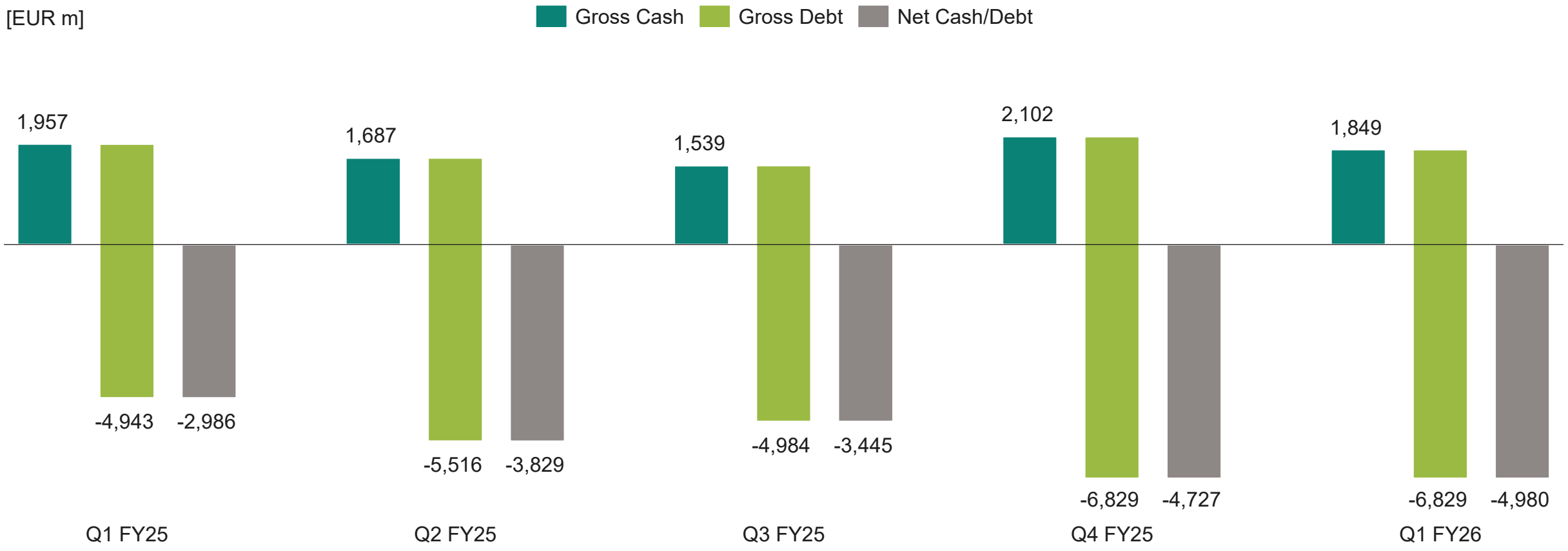


[1] See notes for definition

[2] The calculation of DSO was adjusted effective 1 October 2025. The adjustment increases the transparency and informative value of the key figure and improves its comparability. The figures for the comparative periods have been adjusted accordingly.

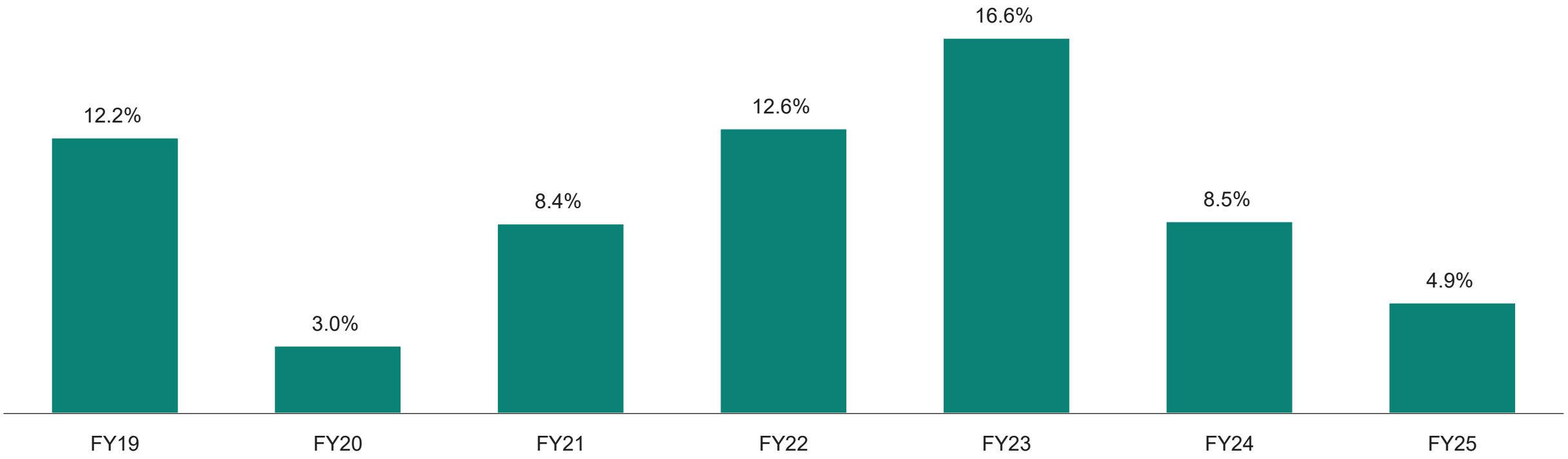
Development of liquidity and debt

Capital structure



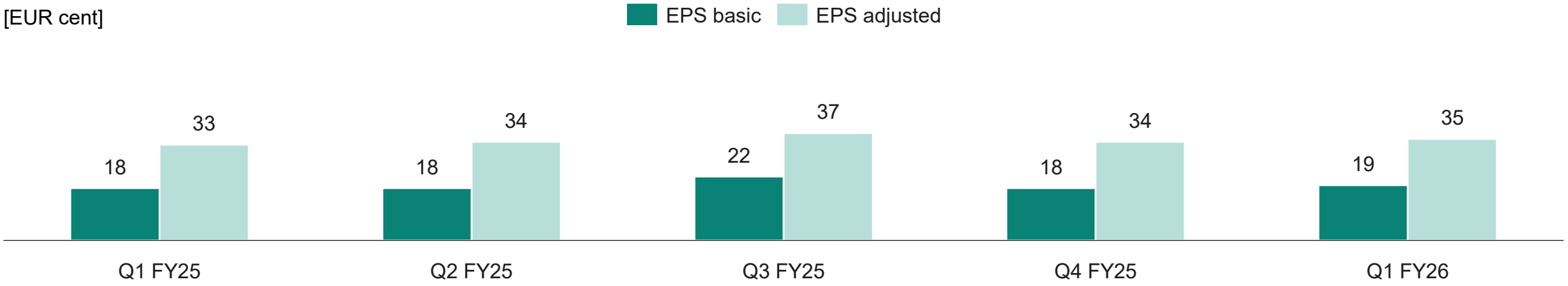
Return on capital employed

Historical development

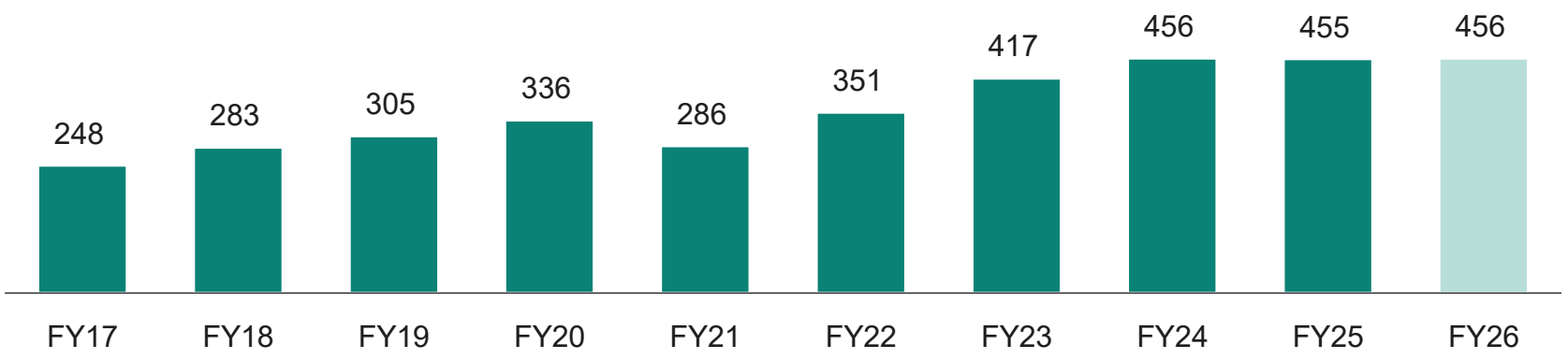


Earnings-per-share and total cash return

Development of earnings-per-share (EPS) from continuing operations



Total cash return to shareholders via dividends

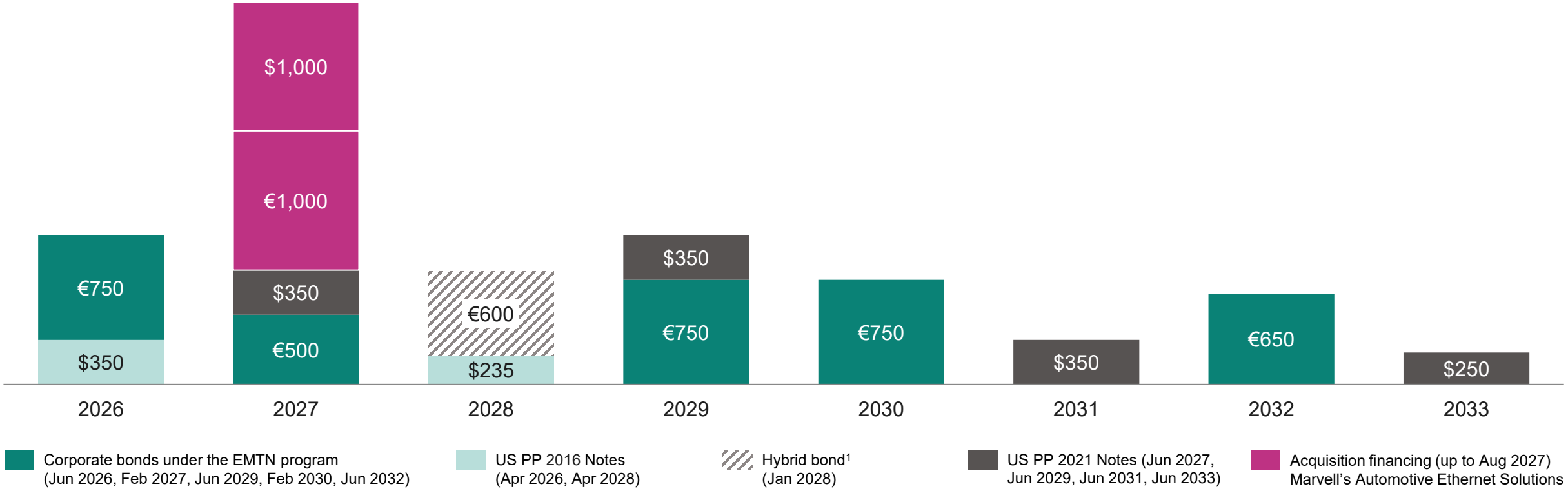


- Proposed dividend for FY25: €0.35 per share
- Payout of €456m

Maturity profile

Calendar years 2026 to 2033

[EUR m; USD m; nominal values]



[1] On 1 Oct 2019, Infineon issued a €600m perpetual hybrid bond with first call date in 2028; the hybrid bond is accounted as equity under IFRS.

Conservative financial policy and strict commitment to investment-grade rating are the basis for through-cycle flexibility

	Financial Policy Targets	Status Quo (LTM 31 December 2025)
Gross Cash[1]	At least **10%** of revenue[3]	12% of revenue → **€1.8bn**
Gross Debt[2]	**≤ 2.0x** EBITDA	**2.0x** EBITDA
Comfortable liquidity position	– Flexibility for financing operating activities and investments through the cycle	
Balanced debt position	– Gross debt target commensurate with investment-grade rating	
Rating	Investment grade	**BBB+** stable outlook (by S&P Global Ratings)

[1] Gross cash position is defined as cash and cash equivalents plus financial investments | [2] Gross debt is defined as short-term debt and current maturities of long-term debt plus long-term debt. EBITDA is calculated as the total of earnings from continued operations before interest and taxes plus scheduled depreciation and amortization | [3] Gross cash target: At least 10 percent of revenue on average throughout the fiscal year


Infineon

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Glossary

AC	alternating current
AD	automated driving
ADAS	advanced driver assistance system
AI	artificial intelligence
BBU	battery back-up unit
BEV	battery electric vehicle
BLE	Bluetooth low energy
BMS	battery management system
BoM	bill of materials
BVM	backside vertical module
DC	direct current
DSC/SSC	double/single sided cooling
E/E	electrical/electronic architecture
ECPD	electronic circuit protection device
ECU	electronic control unit
EMS	electronics manufacturing service
ESS	energy storage system
EV	electric vehicle
FCEV	fuel cell electric vehicle
FHEV/MHEV	full/mild hybrid electric vehicle
GaN	gallium nitride
GPU	graphic processing unit
HEMT	high-electron-mobility transistor
HFT	high-frequency transformation
HV	high voltage
HVAC	heating, ventilation, air conditioning
HVDC	high-voltage direct current
IBC	intermediate bus converter
IC	integrated circuit
ICE	internal combustion engine
IGBT	insulated gate bipolar transistor
IoT	internet of things
LED	light-emitting diode
LLC	resonant tank converter
MCU	microcontroller unit
LV	low voltage
MEMS	micro electro-mechanical system
MOSFET	metal-oxide silicon field-effect transistor
MPU	micro processing unit
MV	medium voltage
NFC	near-field communication
OBC	on-board charger
OEM	original equipment manufacturer
P2S	Infineon's strategic product-to-system approach
PCS	power capacitor system
PFC	power factor correction
PDN	power delivery network
PHEV	plug-in hybrid electric vehicle
PHY	physical layer transceiver
PMIC	power management integrated circuits
PSU	power supply unit
RAM	random access memory
RF	radio frequency
SAE	Society of Automotive Engineers
SAM	serviceable available market
SDK	software development kit
Si	silicon
SiC	silicon carbide
SiVR	substrate integrated voltage regulator
SoC	system-on-chip / state of charge
SSCB	solid-state circuit breaker
SST	solid-state transformer
ToF	time-of-flight
UPS-ESS	uninterruptable power supply energy storage solution
UWB	ultra-wideband
VRM	voltage regulator module
xSC	different switched capacitor topologies

Notes and ESG footnotes

Investments =	'Investments in property, plant and equipment' + 'Investments in other intangible assets and capitalized developments costs'
Adjusted Free Cash Flow Margin =	Adjusted for large investments in frontend buildings and major M&A transactions, for full definition see chapter "Internal management system" in the annual report
Capital Employed =	'Total assets' – 'Cash and cash equivalents' – 'Financial investments' – 'Assets classified as held for sale' – ('Total Current liabilities' – 'Short-term financial debt and current maturities of long-term financial debt' – 'Liabilities classified as held for sale')
RoCE =	'Operating profit from continuing operations'/'Capital Employed' = 'Profit (loss) from continuing operations adjusted for interest result'/'Capital Employed'
Working Capital =	('Total current assets' – 'Cash and cash equivalents' – 'Financial investments' – 'Assets classified as held for sale') – ('Total current liabilities' – 'Short term financial debt and current portion of long-term financial debt' – 'Liabilities classified as held for sale')
DIO (days inventory outstanding; quarter-to-date) =	('Net Inventories'/'Cost of goods sold') x 90
DPO (days payables outstanding; quarter-to-date) =	('Trade payables'/['Cost of goods sold' + 'Purchase of property, plant and equipment']) x 90
DSO (days sales outstanding; quarter-to-date) =	('Trade receivables' - 'reimbursement obligation' + 'contract assets') / 'revenue' x 90

Order backlog =	The total amount of orders received regardless of their current status

ESG footnotes:

1) This figure takes into account manufacturing, transportation, own vehicles, travel, raw materials and consumables, chemicals, water/waste water, direct emissions, energy consumption, waste, etc. as well as direct and indirect energy-related emissions by manufacturing service providers. It is based on data collected internally and publicly available conversion factors and relates to the 2021 fiscal year.
2) This figure is based on internally established criteria, which are described in the explanatory notes. The figure relates to the 2020 calendar year and takes into account the following application areas: automotive, LED, induction cookers, servers, renewable energy (wind, photovoltaic) and cell phone chargers as well as drives. CO_2 savings are calculated based on the potential savings generated by technologies in which semiconductors are used. The CO_2 savings are allocated based on Infineon's market share, semiconductor share, and the lifetime of the technologies concerned, based on internal and external experts' estimations. Despite the fact that carbon footprint calculations are subject to imprecision due to the complex issues involved, the results are nevertheless clear.
3) Carbon neutrality is defined in terms of Scope 1 and Scope 2 emissions.

Financial calendar

Date	Event	Location
19 February 2026	Annual General Meeting 2026	Munich
26 February 2026	SIG Fifteenth Annual Technology Conference	New York
3 March 2026	Morgan Stanley TMT Conference	San Francisco
5 – 6 March 2026	Oddo BHF TMT Forum	virtual
9 March 2026	BNP Paribas Exane TMT Conference	London
10 March 2026	Citi TMT Conference	London
19 March 2026	Bernstein ESG Conference	Paris
6 May 2026[1]	Earnings release for the second quarter of the 2026 fiscal year	
5 August 2026[1]	Earnings release for the third quarter of the 2026 fiscal year	
10 November 2026[1]	Earnings release for the fourth quarter and the 2026 fiscal year	

[1] Preliminary

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